

University of Wisconsin-Madison Materials Research Science and Engineering Center Facilities Days Open House 2018

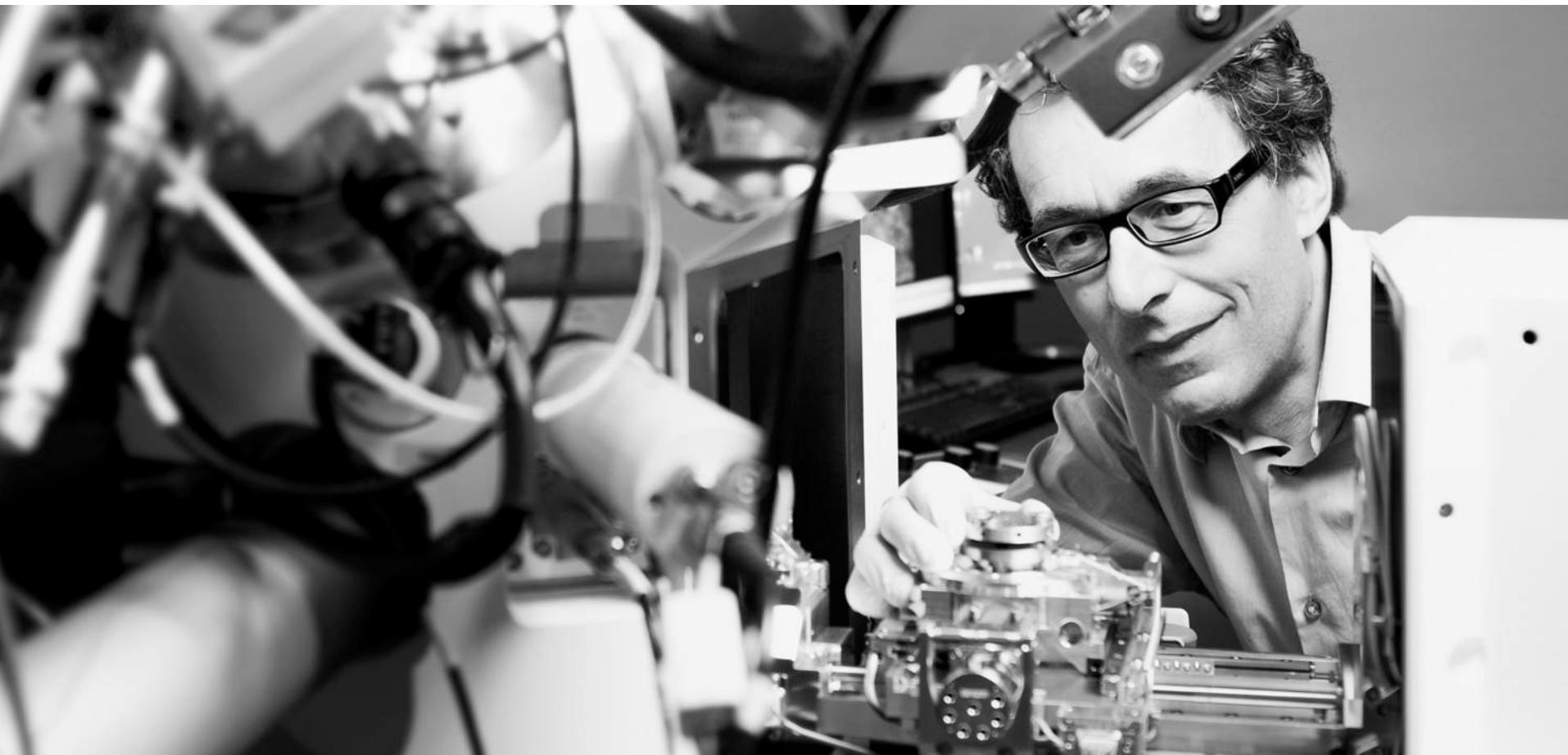


Two atoms were walking down the street when one said, "Oh my, I've lost an electron!" The other said, "Are you sure?" "Yes, I'm positive!".

Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



Facilities Days Open House 2018



Chris Santeufemio

Senior Applications Engineer
Thornwood, NY, 2018-04-09

Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



Facilities Days Open House 2018

Christopher Santeufemio

Senior Applications Engineer

Carl Zeiss Microscopy

Chris is a career-long Electron Microscopist, with 30 years of experience in Microscopy. First used a Zeiss TEM as undergrad. Has been a Zeiss customer for his whole career, and just recently joined Zeiss as Senior Applications Engineer in 2016.

He split his career between Biological and Material Science, working in Ultrastructural Pathology and Neuroanatomy at Hartford Hospital, St. Barnabas Medical Center, and McLean Hospital. Chris worked at Raytheon doing SEM, Metrology, Failure Analysis and Material Science, and at Epion Corporation where he helped develop the Gas Cluster Ion Beam system for Materials Applications.

At the University of Massachusetts, Lowell, Materials Characterization Lab, Chris managed the operation of 2 SEMs, 2 FESEMs, 3 TEMs, 3 AFMs, an E-Beam Lithography system and a FIB-SEM housed in a new, state of the art Emerging Technologies Center.

Gaining more business expertise, Chris worked with MicroVision Labs as Senior Analyst and VP of Business Development. He has extensive experience in TEM, SEM, STEM, FIB-SEM, AFM and Optical Microscopy.



Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



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Intro

The scanning electron microscope (SEM) is a type of microscope that produces images of a sample by scanning the surface with a focused beam of electrons.

The electrons interact with atoms in the sample, producing various signals that contain information about the sample's surface topography and composition.

The electron beam is scanned in a raster scan pattern, and the beam's position is combined with the detected signal to produce an image.

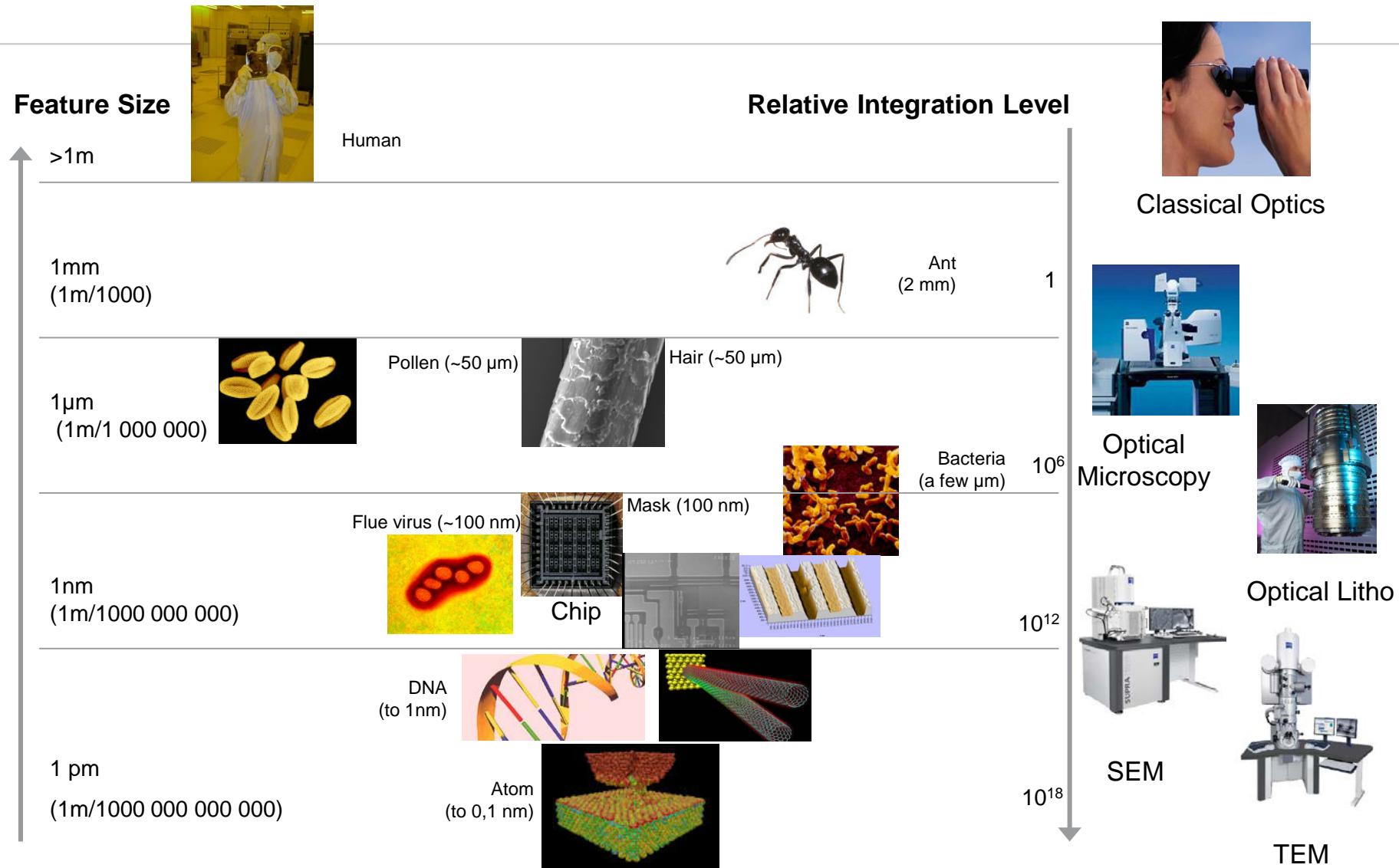
SEM can achieve resolution better than 1 nanometer, or 1×10^{-9} meters

Specimens can be observed in high vacuum in conventional SEM, or in low vacuum or wet conditions in variable pressure or environmental SEM, and at a wide range of cryogenic or elevated temperatures with specialized instruments.

Characteristic X-rays that are produced by the interaction of electrons with the sample may also be detected in an SEM equipped for energy-dispersive X-ray spectroscopy

Analysis of the x-ray signals can be used to map the distribution and estimate the abundance of elements in the sample.

Overview of Micro and Nano Technology Solutions



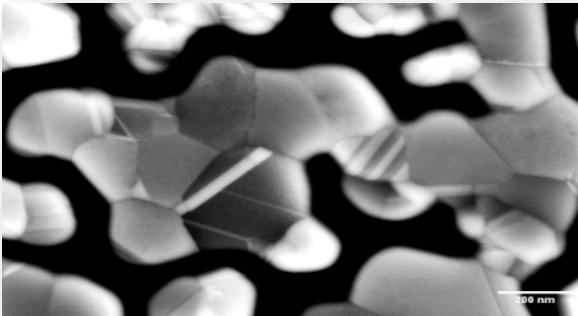
SEM offers Diverse Applications



Materials Science

**Basic Materials,
Functional Materials,
Nanomaterials,
2D Materials**

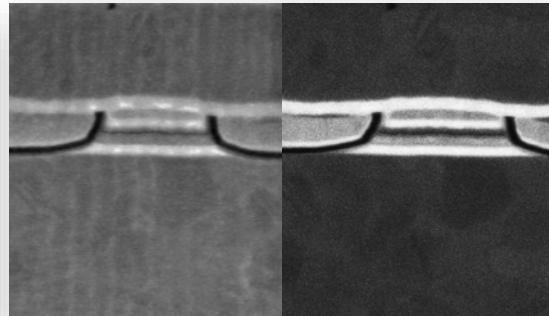
**Metals, Alloys
Ceramics, Minerals,
Polymers, Composites**



Industry

**Semiconductor
Data Storage,
Telecom, Flat Panel
Electronics
Battery, Solar**

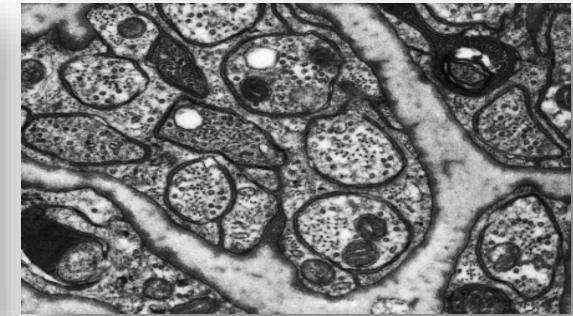
**Silicon, Resist, Metals,
Particles, Catalyst**



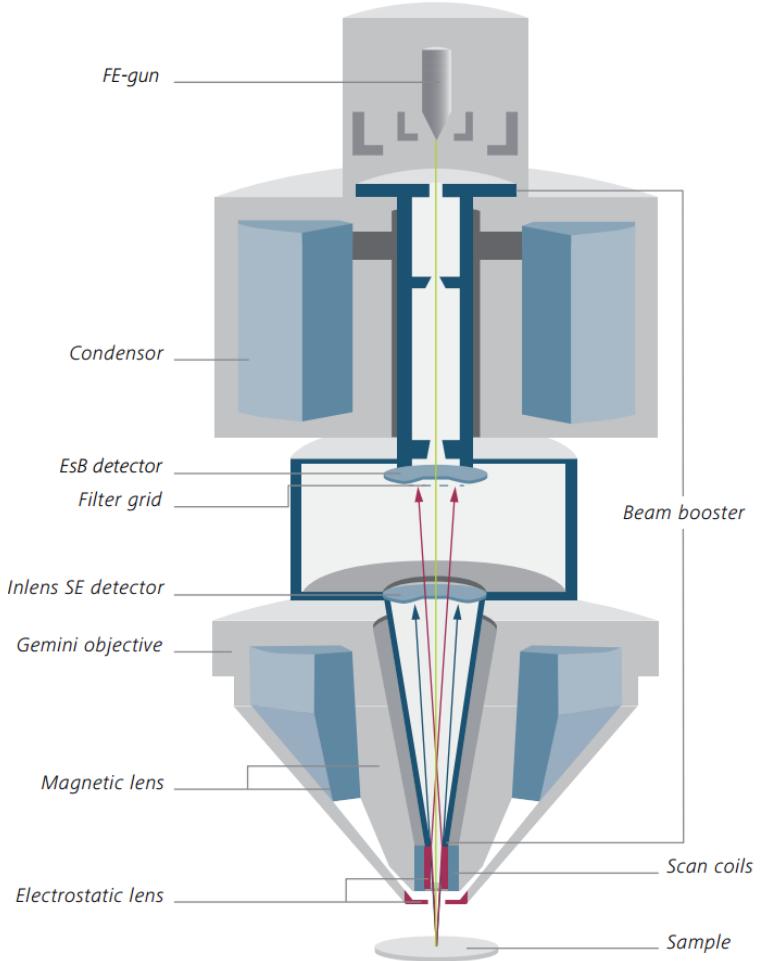
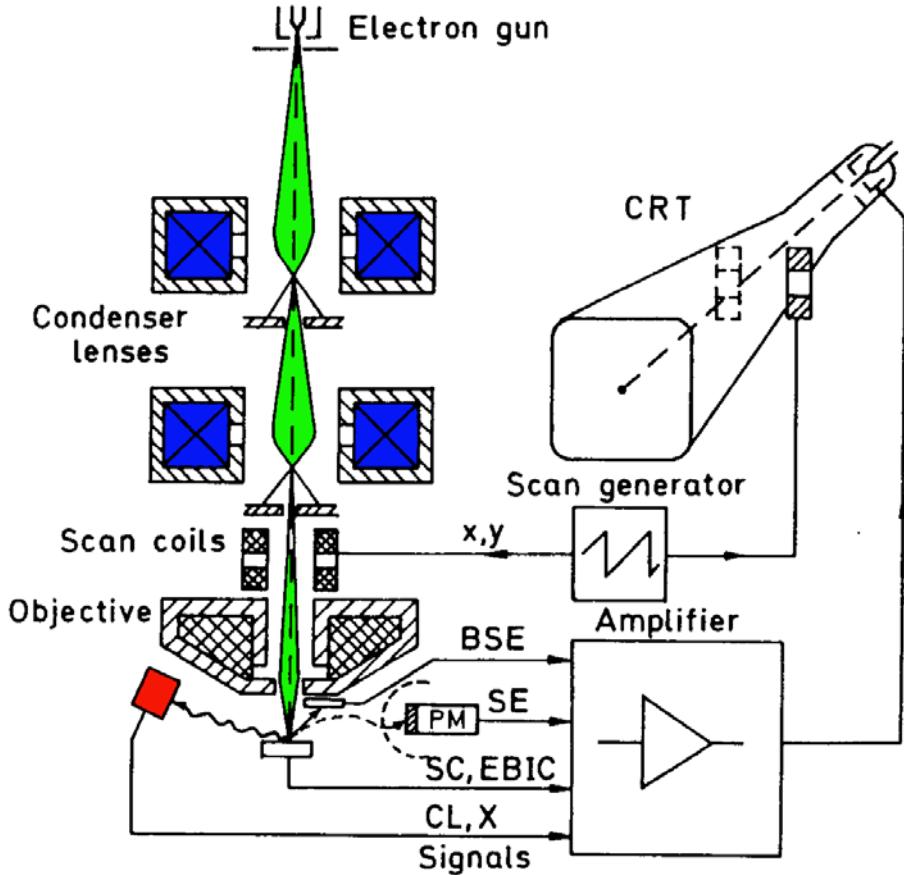
Life Science

**Bio, Pharma,
Cosmetics,
Medical Diagnostics,
Brain Research**

**Nano Bio Tech
Drugs, Cells, Tissues**

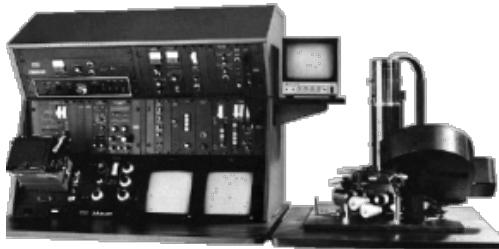


Scanning Electron Microscopes



Schematic of a SEM

Recent Historical SEMs - 1900s



ETEC Autoscan



ETEC Bioscan



Bausch & Lomb Nanolab
LE2100



Perkin Elmer Hitachi HFS-2



ISI Mini-SEM



Zeiss 982 Gemini



ISI Super 3A (40)



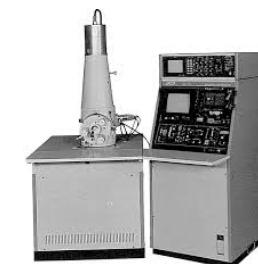
Cambridge 600



Amray 1000



Amray 1200



JEOL JSM-35



Cambridge 180



ISI DS-130



Hitachi S800

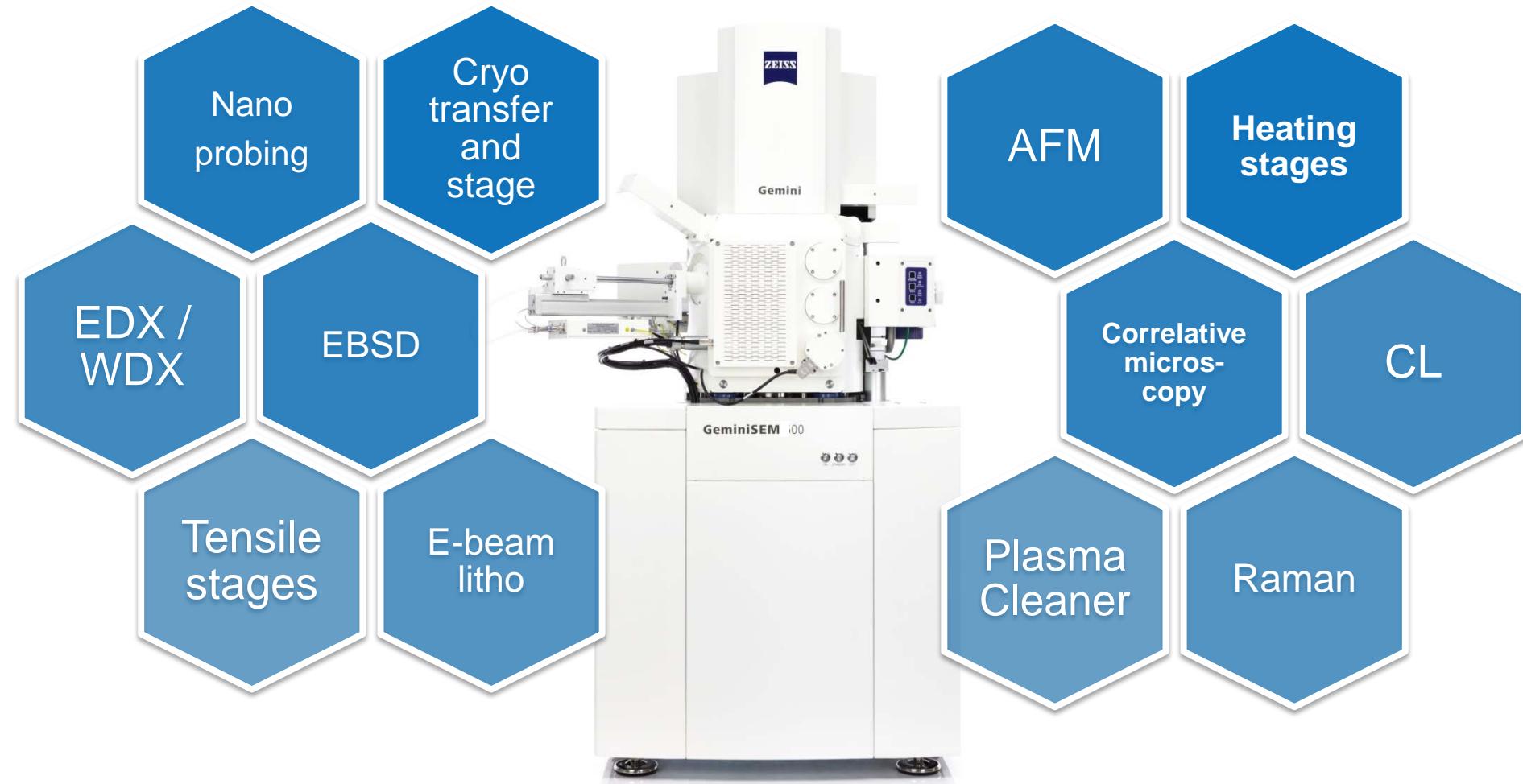


Hitachi TM-1000



Coates & Welter
CWIKSCAN/100

State of the Art SEM systems offer Flexibility to Seamless Integration of 3rd Party Accessories and *in situ* Experiments



Nano probing

Cryo transfer and stage

EDX / WDX

EBSĐ

Tensile stages

E-beam litho

AFM

Heating stages

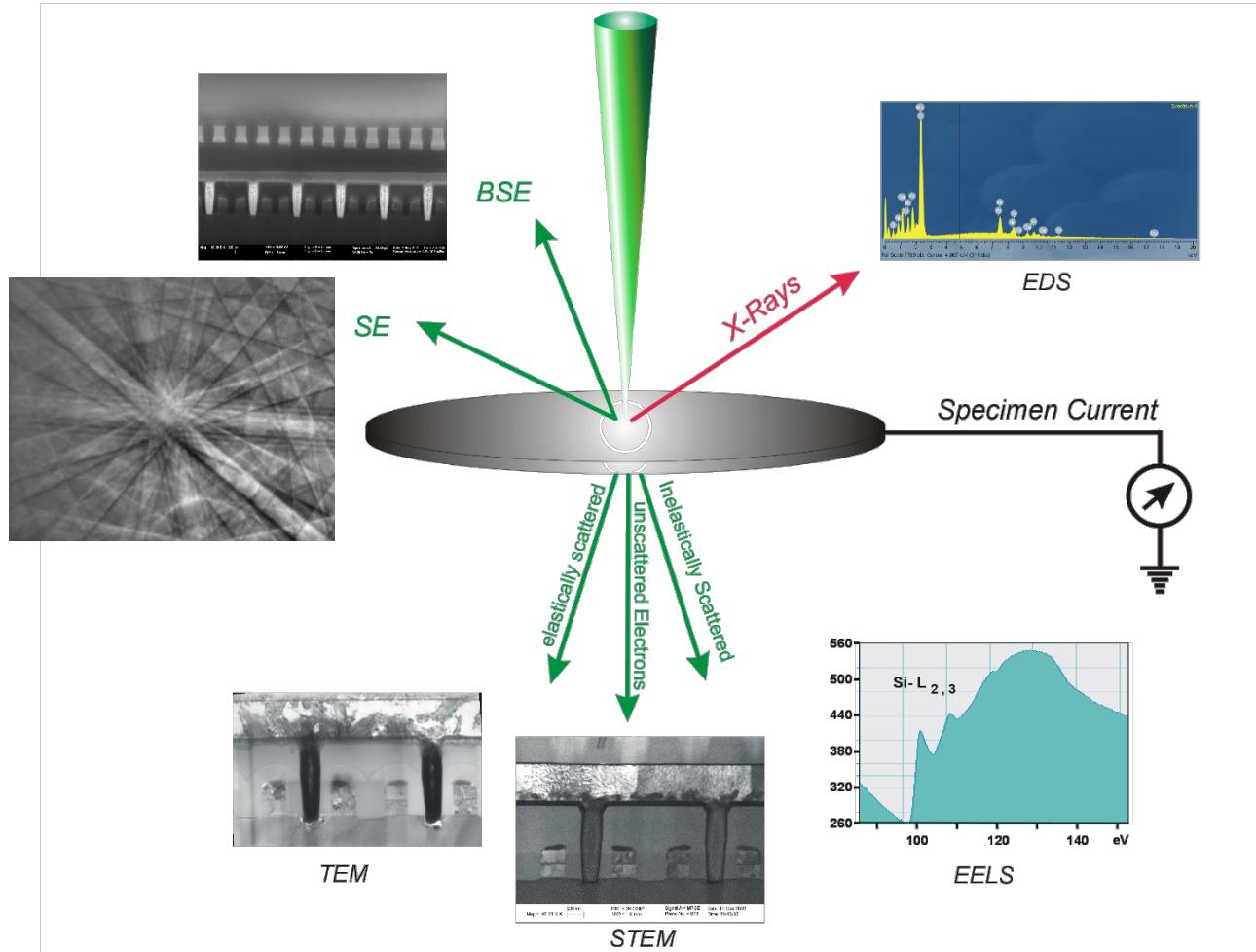
Correlative microscopy

CL

Plasma Cleaner

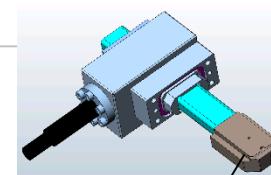
Raman

Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy

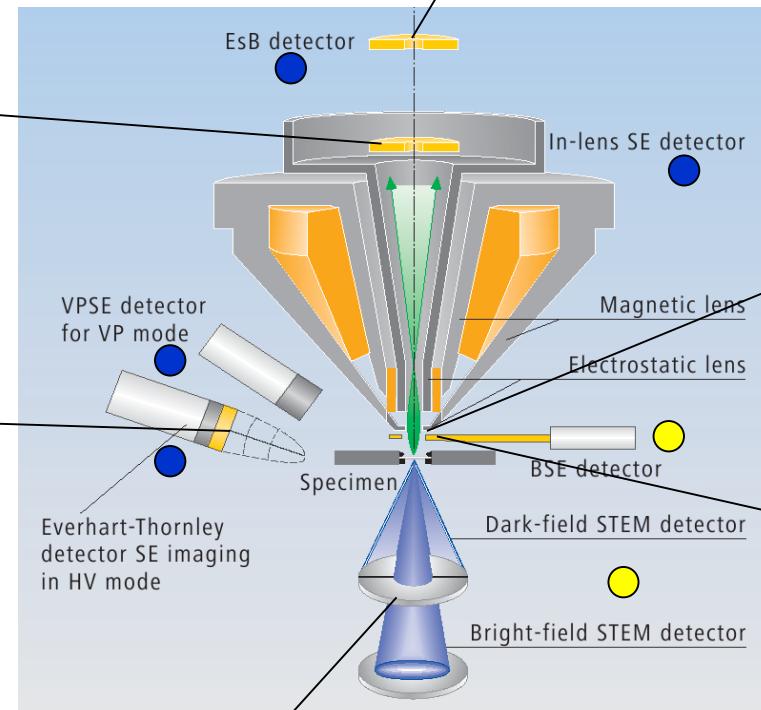
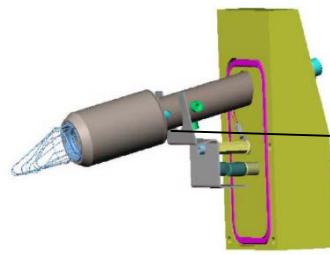


Beam Sample interaction

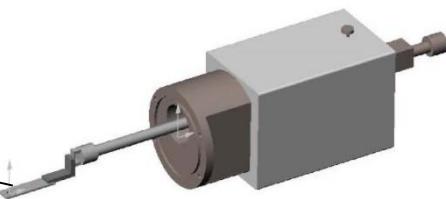
Various Electron Detectors



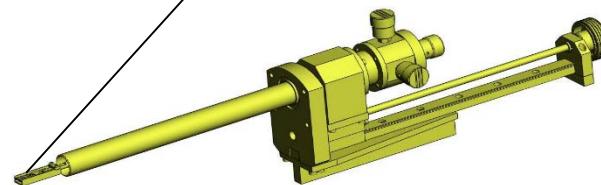
Energy selective Backscatter detector (EsB)



Angle selective Backscatter detector (AsB)



Retractable BSE Detector



- Scintillator Detector
- Semiconductor Detector

Comparison of Various Microanalytical Techniques



Name	Energy in	Energy out	Resolution		Detection Limit	Lightest Element	Imaging	Other Info	Comments
			Lateral	Depth					
SEM	e- (2 - 30 keV)	SE (50eV)	1 nm	5 nm	1000 ppm	Be	Yes		Routine, easy sample
EDS		BSE (Eo)	<0.1 um	<0.5 um			Yes		Prep good imaging and analysis
		X-rays (>108 eV)	<0.1 um	<0.5 um			Yes		
EPMA	e- (5 - 50 keV)	X-rays (>108 eV)	<0.5 um	<0.5 um	50 ppm	Be	Yes		Quantitative surface
WDS									
TEM	e- (100 keV - 1MeV)	TE (Eo)	0.2 nm	<100 nm	1000 ppm	Be	Yes	SAED	High resolution, electron diffraction
AEM	e- (200 - 400 keV)	TE (Eo)	0.2nm	<100 nm		B	Yes	CBED	Analytical resolution
STEM		SE (50 ev)	3 nm	3 nm		B	Yes		
EDS		X-ray (>108 ev)	5 nm	<100 nm	1000 ppm	Be	Yes		
EELS		electrons	20 nm	<10 nm	1000 ppm	Li	Yes		
AES	e- (1 - 3 keV)	e- (<200 ev)	~0.2 um	<3 nm	1000 ppm	Li	Yes		Quantitative surface analysis
XPS/ESCA	X-rays (1 - 1.5 keV)	e- (>10 ev)	0.5 nm	<3 nm	1000 ppm	He	No	binding energy	Chemical state information
SIMS	ions (4 - 15 keV)	secondary ions	5 um	0.1 nm	1 ppb	H	some	depth profile, mass	Non-destructive depth profile
PIXE	H+, He++ (~3 MeV)	X-rays	2 um		1 ppm	B	some		Analytical sensitivity
RBS	H+, He++ (2 - 25 MeV)	H+ He++ (<Eo)	2 mm	10 nm	1 - 1000 ppm	Li	No	depth profile, mass	Non-destructive depth profile
LIMA	UV (250 nm)	ions	~2 um	~2 um	1 ppm	H	Yes	mass	Analytical sensitivity, mass spectrum
LAMMA									
MicroRaman	visible light ~500 nm	visible light	~2 um				some	molecular spectrum	Phase identification
MicroFTIR	IR light	reflected or transmitted IR	10 um				some	molecular spectrum	Phase and functional group identification
Micro-XRF	X-rays 1-100keV	>1keV	25um-1mm	>1mm	50ppm	Na	Yes		Quantitative surface

Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



The Four Basic Parameters

The Four Basic Parameters



- ✓ **Accelerating Voltage** (EHT)
- ✓ **Aperture Size** (diameter)
- ✓ **Spot Size** (High Current mode)
- ✓ **Working Distance** (sample to lens distance)

Accelerating Voltage



High kV

- Higher resolution
- Greater beam penetration
- Higher beam current
- Higher signal to noise
- More x-ray yield
- Good for VP

Low kV

- Lower resolution
- Less beam penetration
- Lower beam current
- Lower signal to noise
- Lower x-ray yield
- Not so good for VP

Small Aperture

- Higher resolution
- Higher depth of focus
- Lower beam current
- Lower signal to noise
- Less x-ray yield
- May have smaller field of view (aperture cut-off)
- Not so good for VP

Large Aperture

- Lower resolution
- Less depth of focus
- Higher beam current
- Higher signal to noise
- Higher x-ray yield
- Good for VP

Small Spot Size

- Higher resolution
- Lower beam current
- Lower signal to noise
- Less x-ray yield

Large Spot Size

- Lower resolution
- Higher beam current
- Higher signal to noise
- Higher x-ray yield
- Good for VP

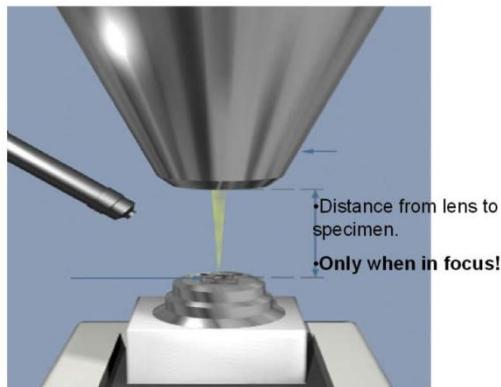
Note: Spot size must be adjusted as a function of final field of view (magnification); i.e. the higher the magnification, the smaller the spot size and visa versa

Short Working Distance

- Higher resolution
- Less Depth of Focus
- Better collection efficiency for In-Lens, AsB and EsB detectors
- Good for VP

Long Working Distance

- Lower resolution
- Greater Depth of Focus
- Better collection efficiency for In-Chamber SE
- Not so good for VP

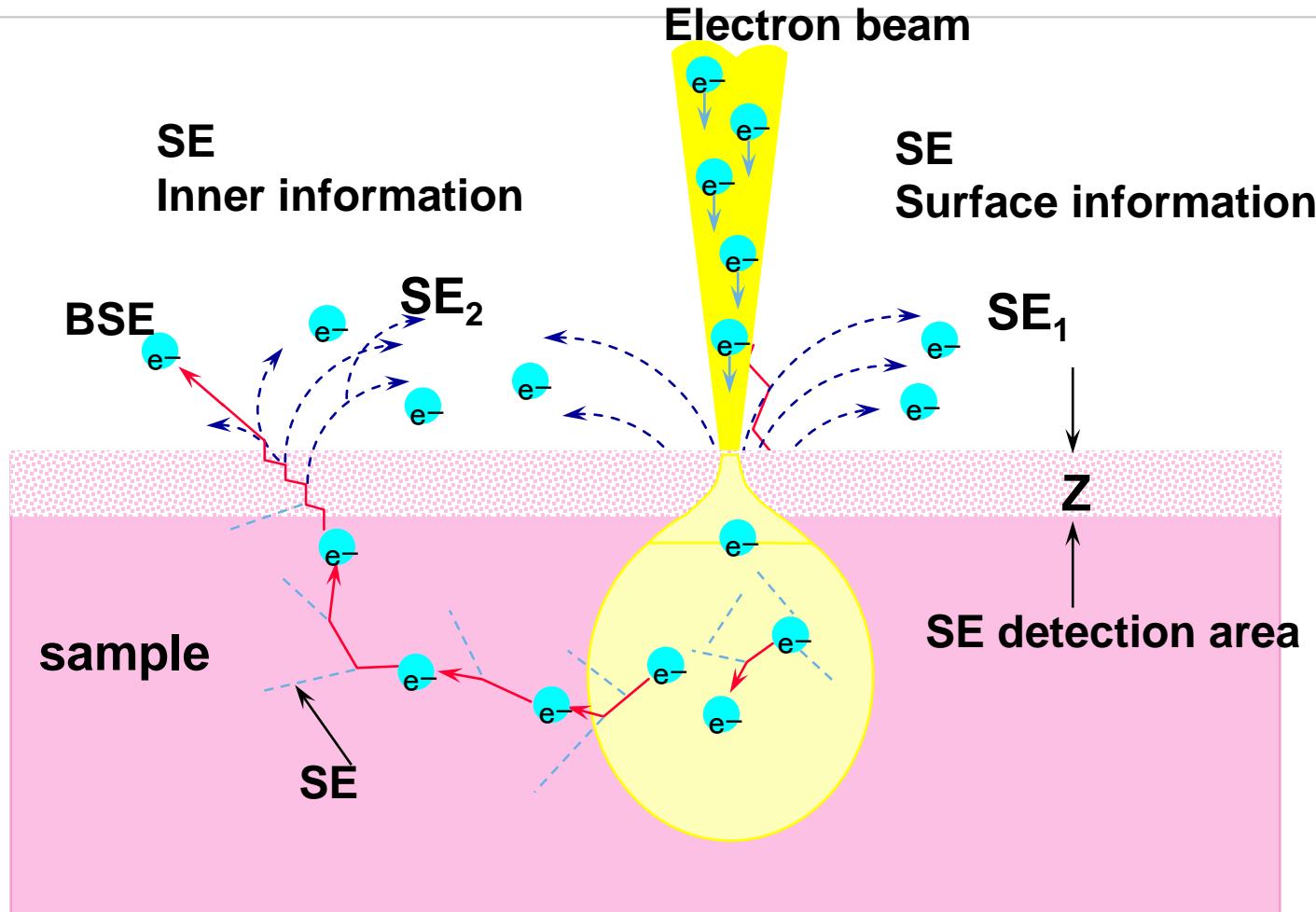


Variables Involved in Image Formation



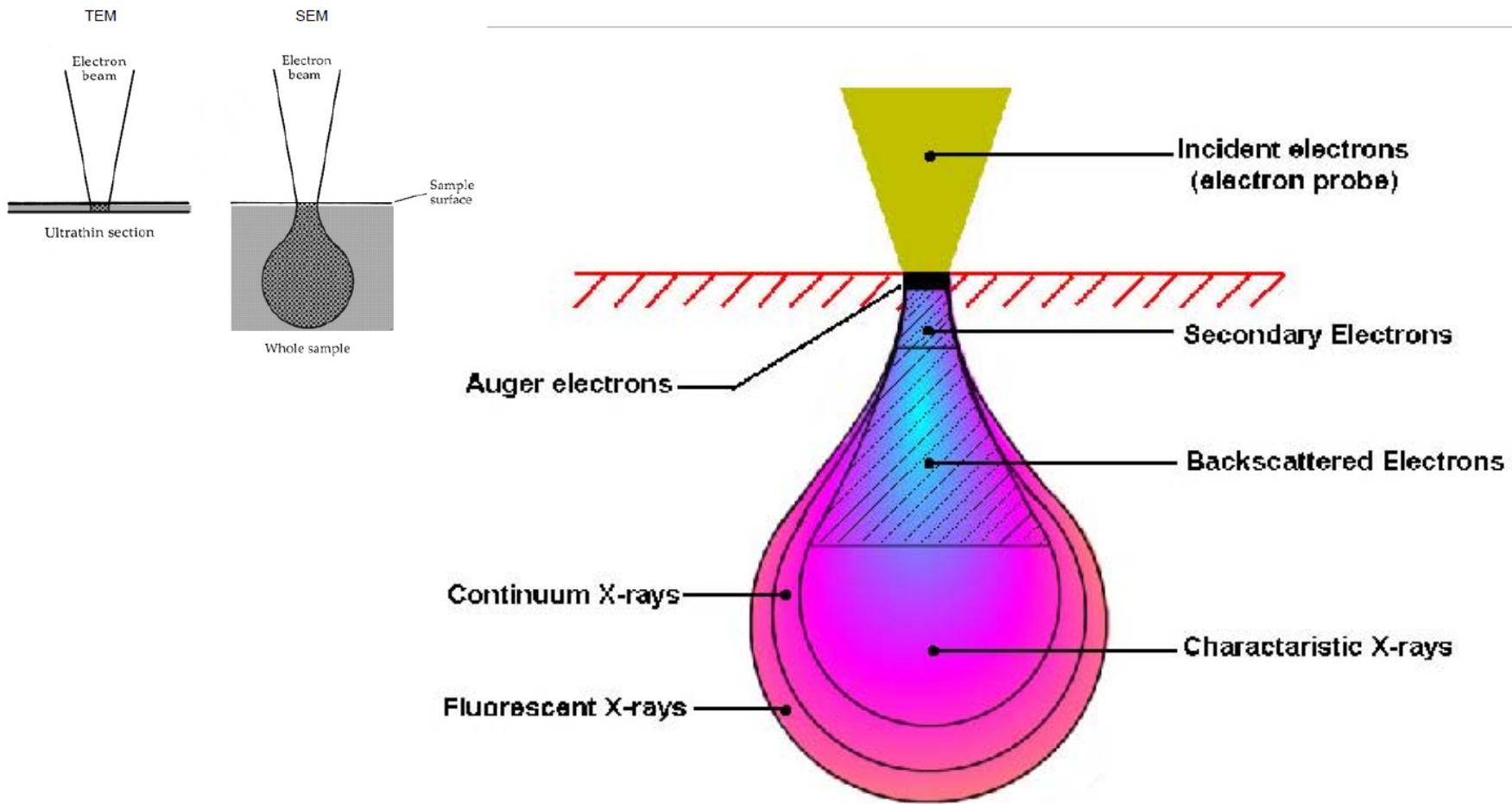
- ✓ Acceleration Voltage (kV)
- ✓ Final Aperture (size)
- ✓ Probe Current (I probe)
- ✓ Working Distance (WD)
- ✓ Specimen
- ✓ Column/Aperture Alignment
- ✓ Detector
- ✓ Specimen geometry
- ✓ Scanning speed
- ✓ Signal processing
- ✓ Noise reduction
- ✓ Contrast / brightness
- ✓ Chamber pressure
- ✓ System cleanliness

Electron Beam Interaction of SE and BSE



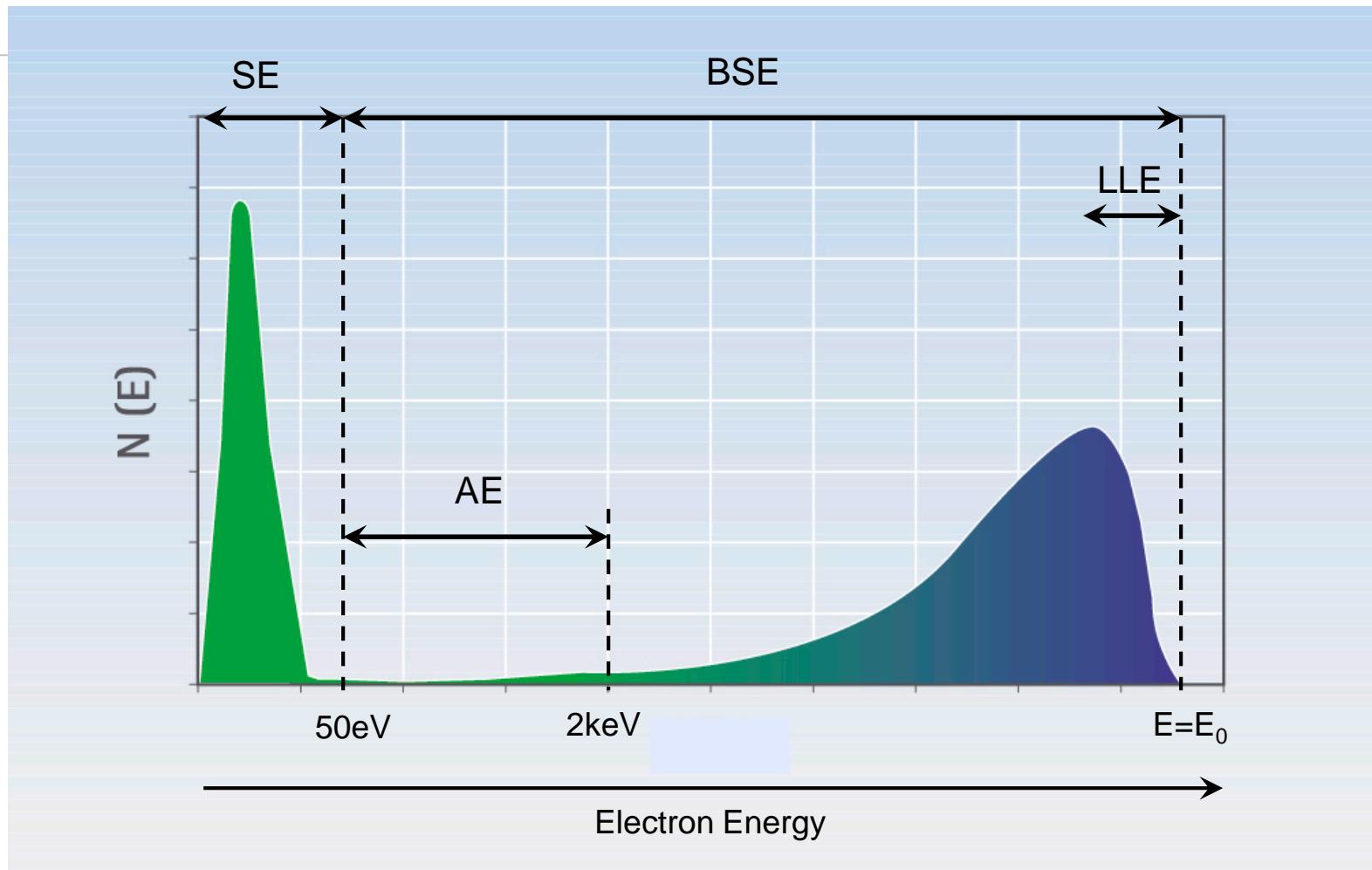
Secondary electrons are emitted from the top 10nm of the sample surface by initial interaction with the sample (SE1) and when a backscatter electron leaves the sample (SE2).

Beam Interaction Diagram



Electron Beam Interaction Diagram

Beam Sample Interaction



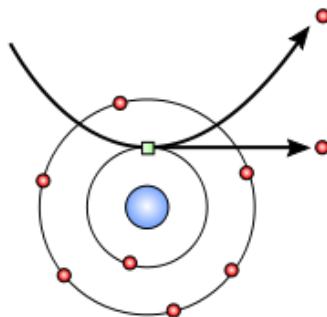
Energy distribution of electrons emerging from the specimen consisting of secondary electrons SE with $E_{SE} \leq 50\text{eV}$, low-loss electrons (LLE) with energy losses of a few hundred eV, back-scatter electrons (BSE) with $E_{BSE} \geq 50\text{eV}$ and Auger electrons (AE)

On-Axis In Column Detection System

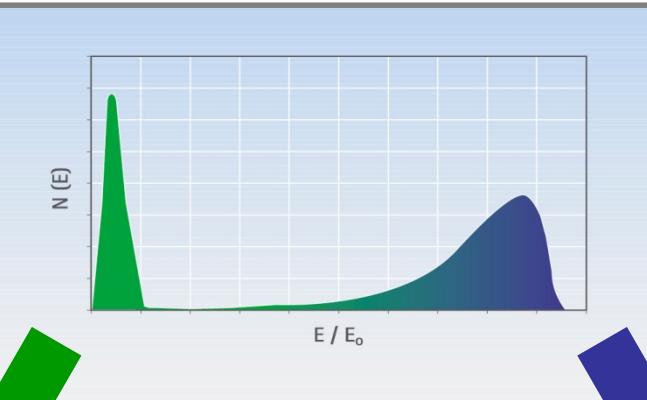
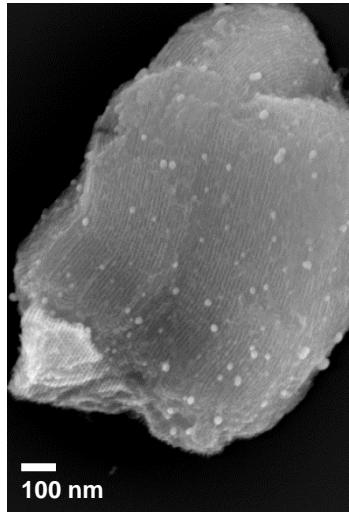
Different electrons carry different information



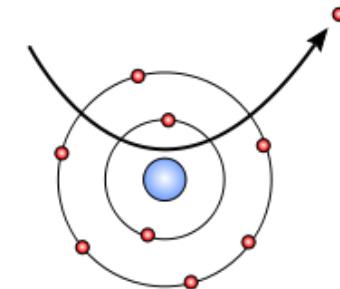
Secondary electrons



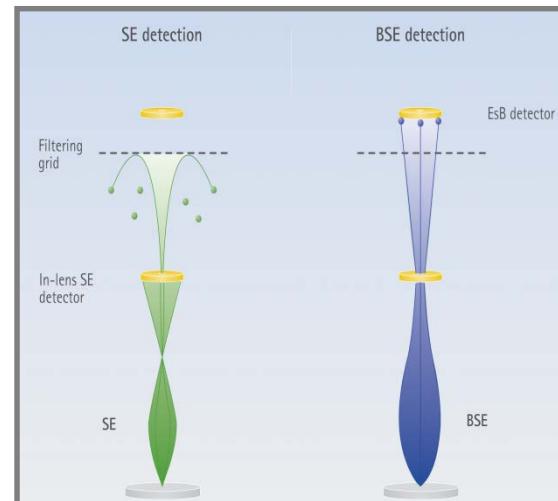
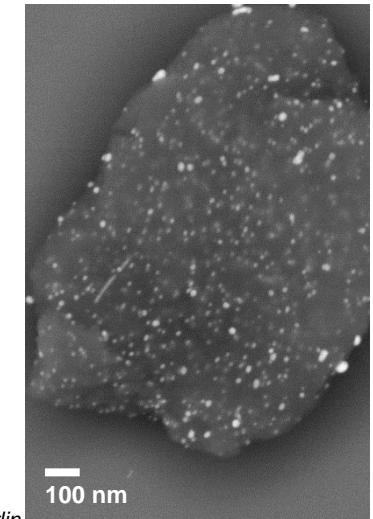
Topographical information



Backscattered electrons



Compositional contrast



Combined detection for maximum information!

Image: Zeolite with Ag nanoparticles, 5kV. Sample courtesy of Fritz-Haber-Institute Berlin

Types of detectable electrons

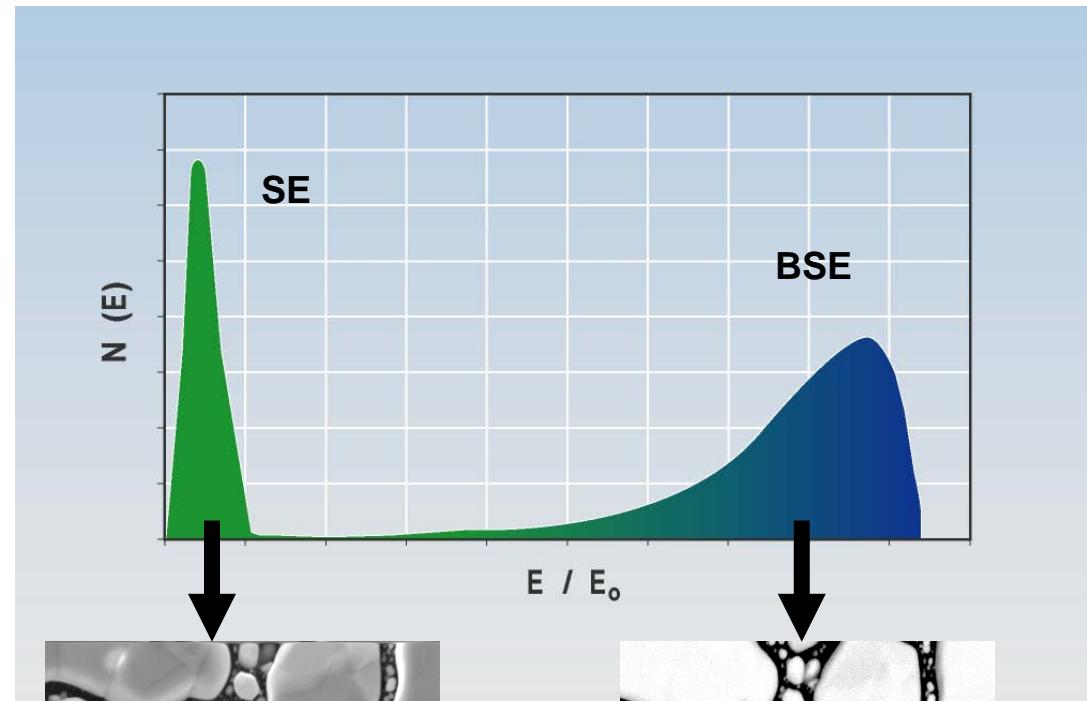
Interaction of primary electrons with sample

Secondary Electrons (SE):

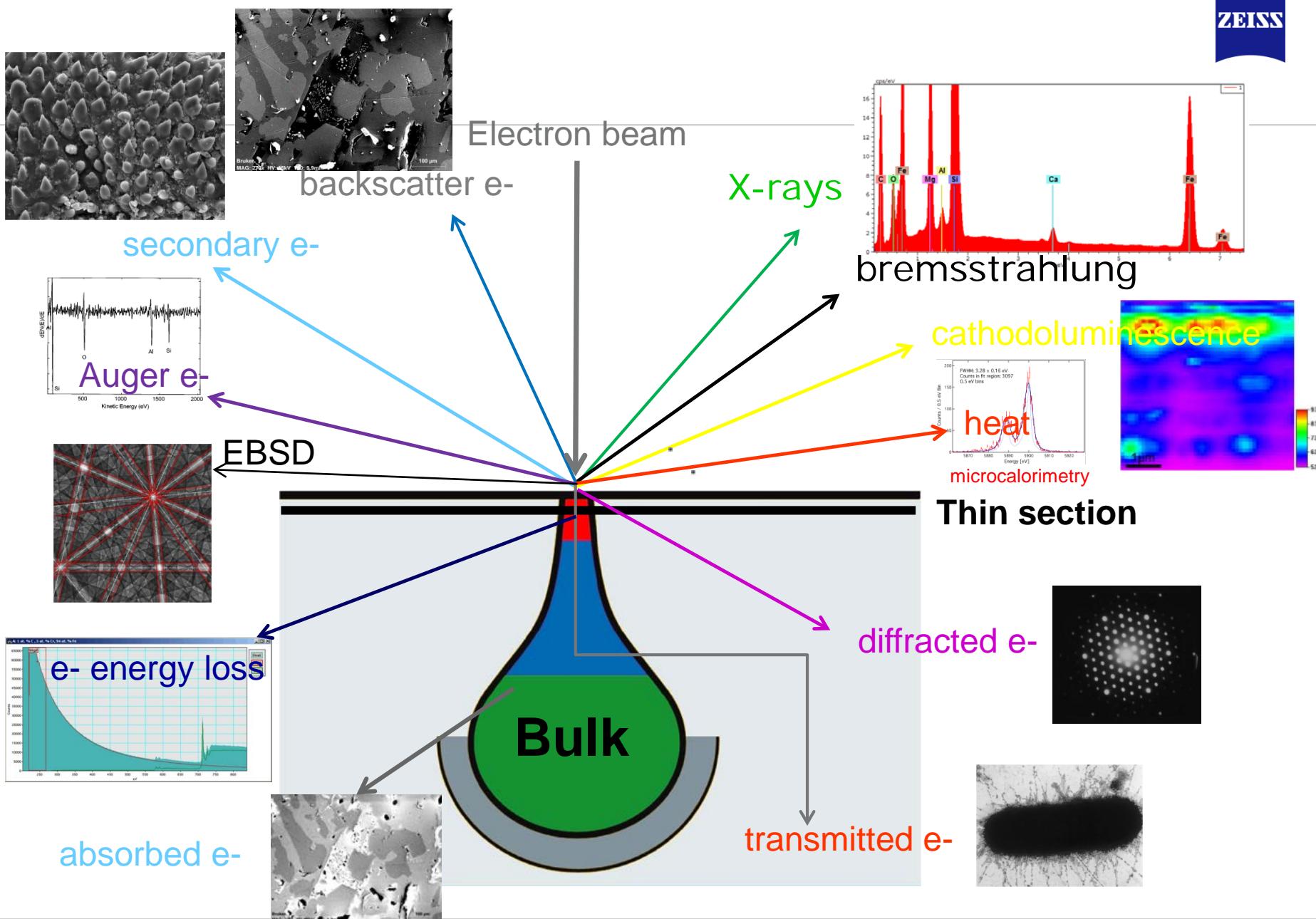
- Inelastic collisions,
- Interaction with surface
- Topographic information
- energy up to 50eV
- SE1: resulting from interactions with primary beam
- SE2: resulting from interactions with BSE in specimen
- SE3: resulting from interactions of BSE with metal parts

Backscatter Electrons (BSE):

- Often elastic collisions
- Interactions with bulk material
→ material information
(Density, Compositions, Z-Contrast, crystal structure)



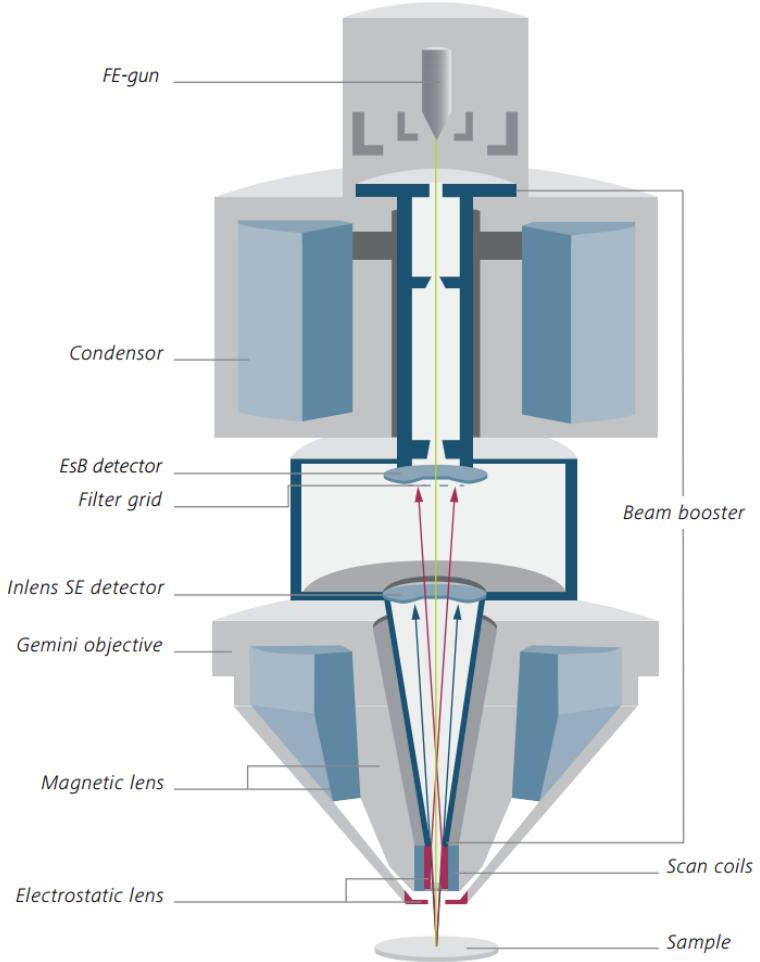
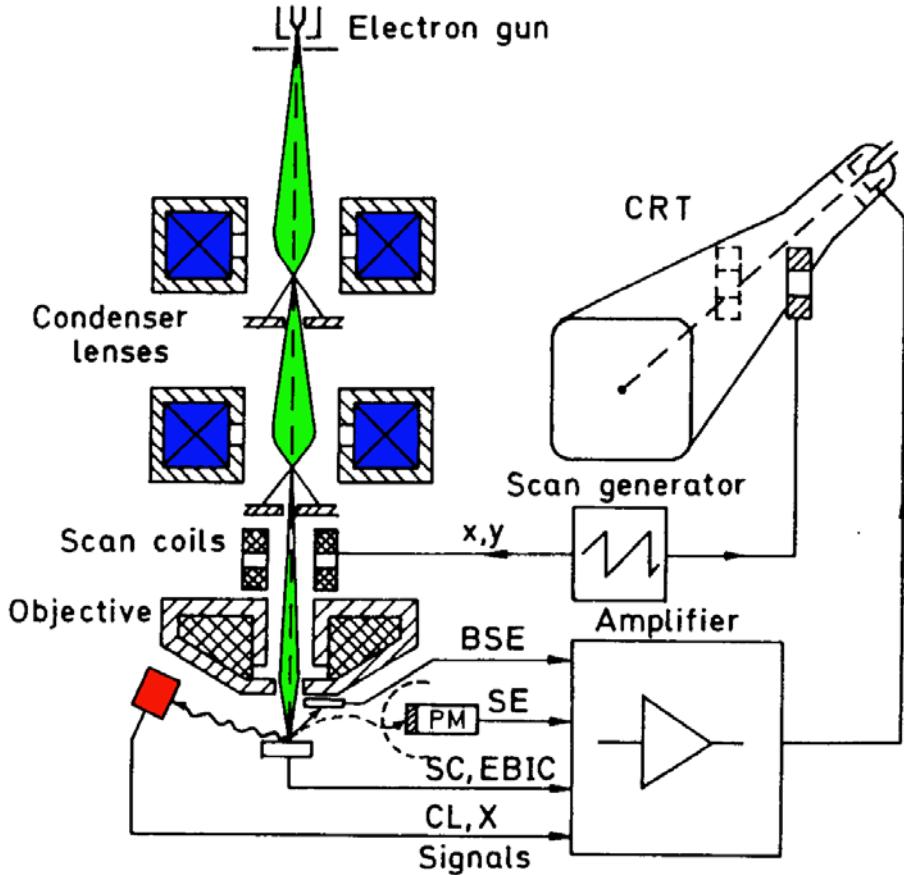
Electron interactions



Electron Guns

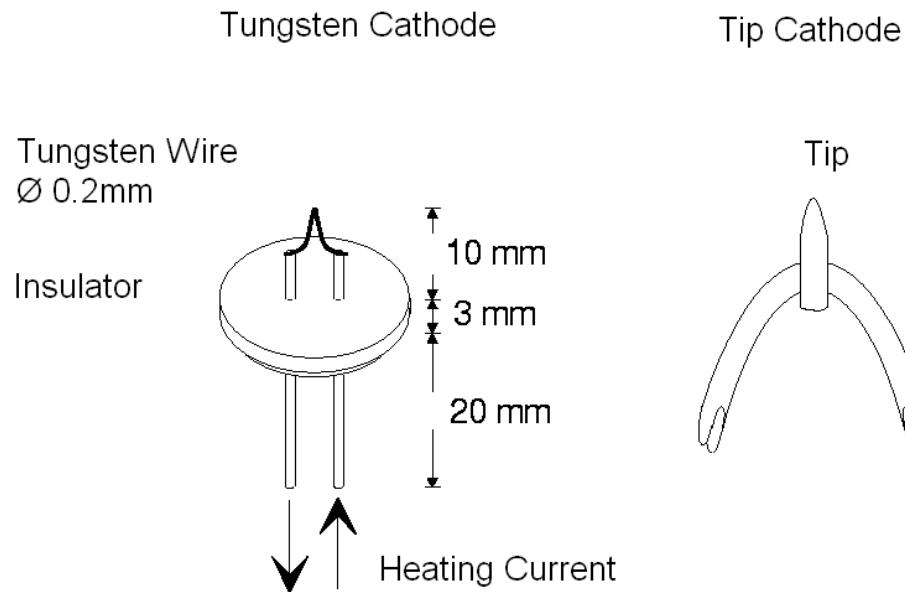


Scanning Electron Microscopes



Schematic of a SEM

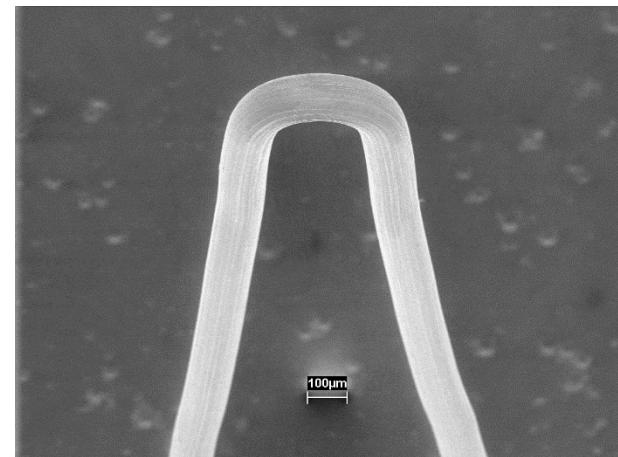
Emission Systems Thermionic Emitters



Schematic of tungsten emitter

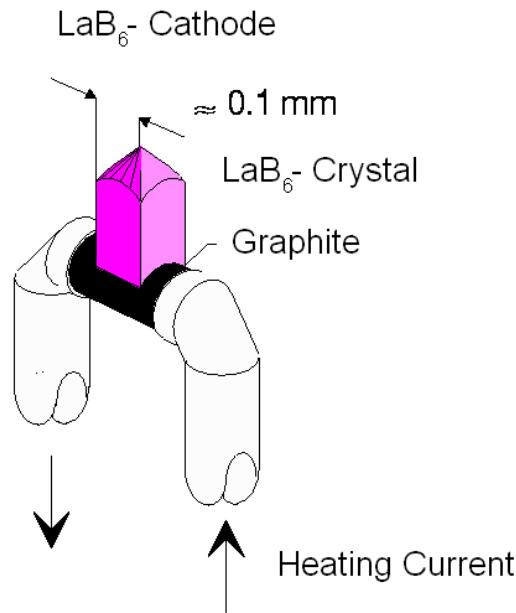


Emitter with Wehnelt assembly

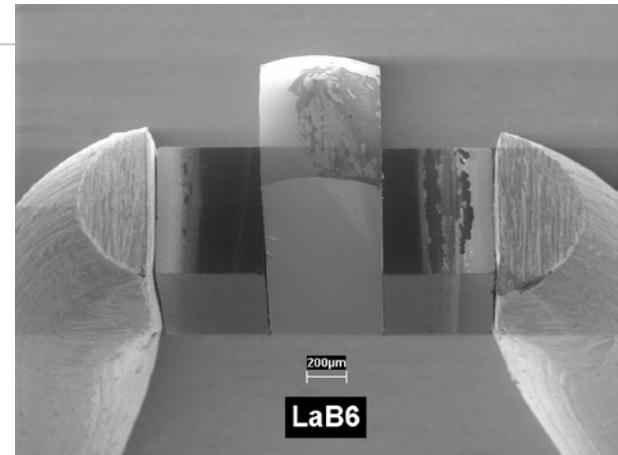


W – Emitter SEM Image

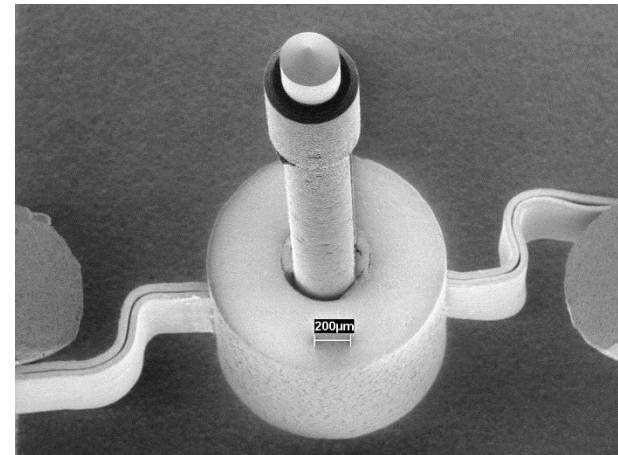
Emission Systems Thermionic Emitters – LaB₆



Schematic of a LaB₆ - Emitter

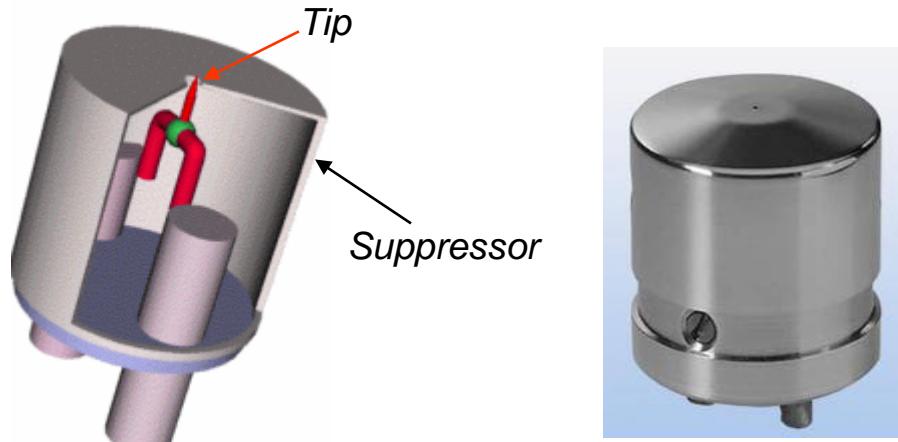


LaB₆ – Emitter SEM Image

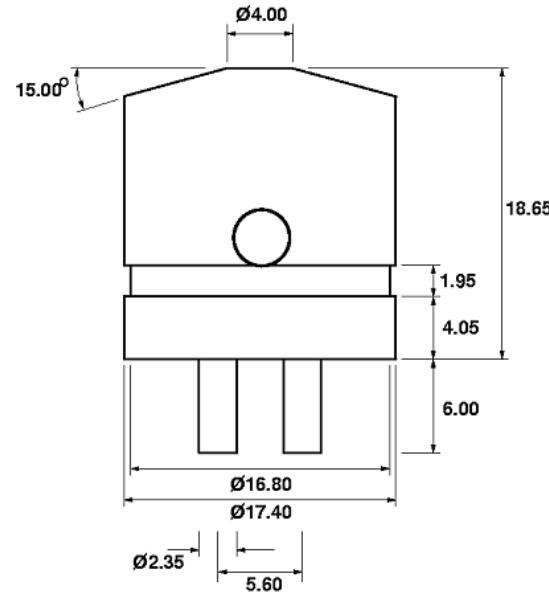


LaB₆ – Emitter SEM Image

Emission Systems: Schottky - Field Emitters

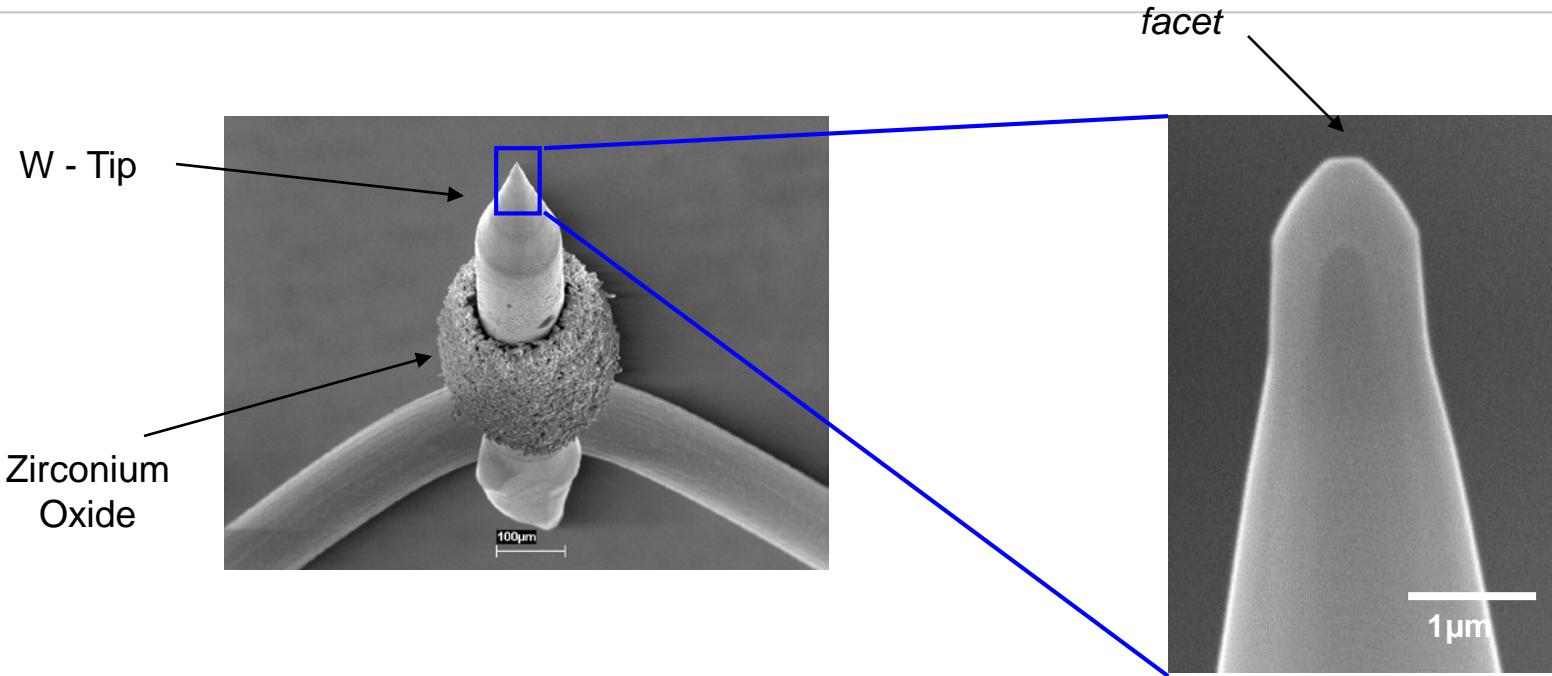


Schottky Emitter – Suppressor Cartridge



A single crystal tungsten wire with a sharp end etched to a small radius (red in the sketch) is mounted on a tungsten hairpin (also red). A current through the filament is used to maintain the **tip** at a temperature of 1750 - 1850 K. The tip just penetrates a hole in a cylindrical **suppressor** electrode mounted around the assembly. Electrons are emitted from the tip due to both thermal excitation and the electric field at the tip due to the potential difference between it and an **extractor** electrode (not shown). Electrons from the filament are repelled by the potential on the suppressor.

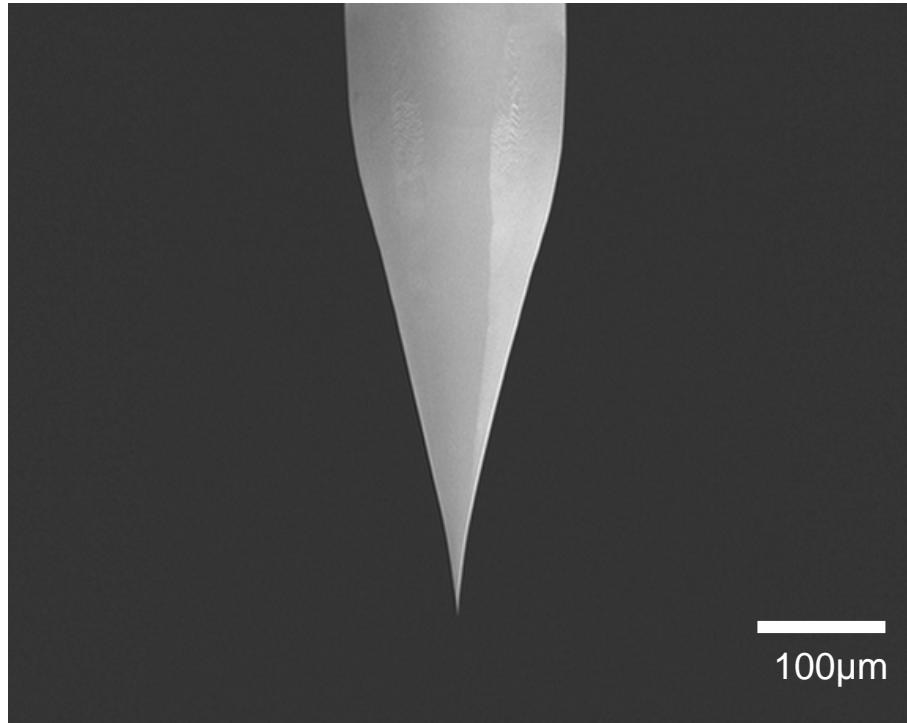
Emission Systems: Schottky - Field Emitters



SEM image of a Schottky tip.

Emission occurs from the crystalline facet (horizontal at the top) that is about 0.3 μm across.

Emission Systems: Cold Field Emitters



Cold Field Emitter - SEM Micrograph

Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy

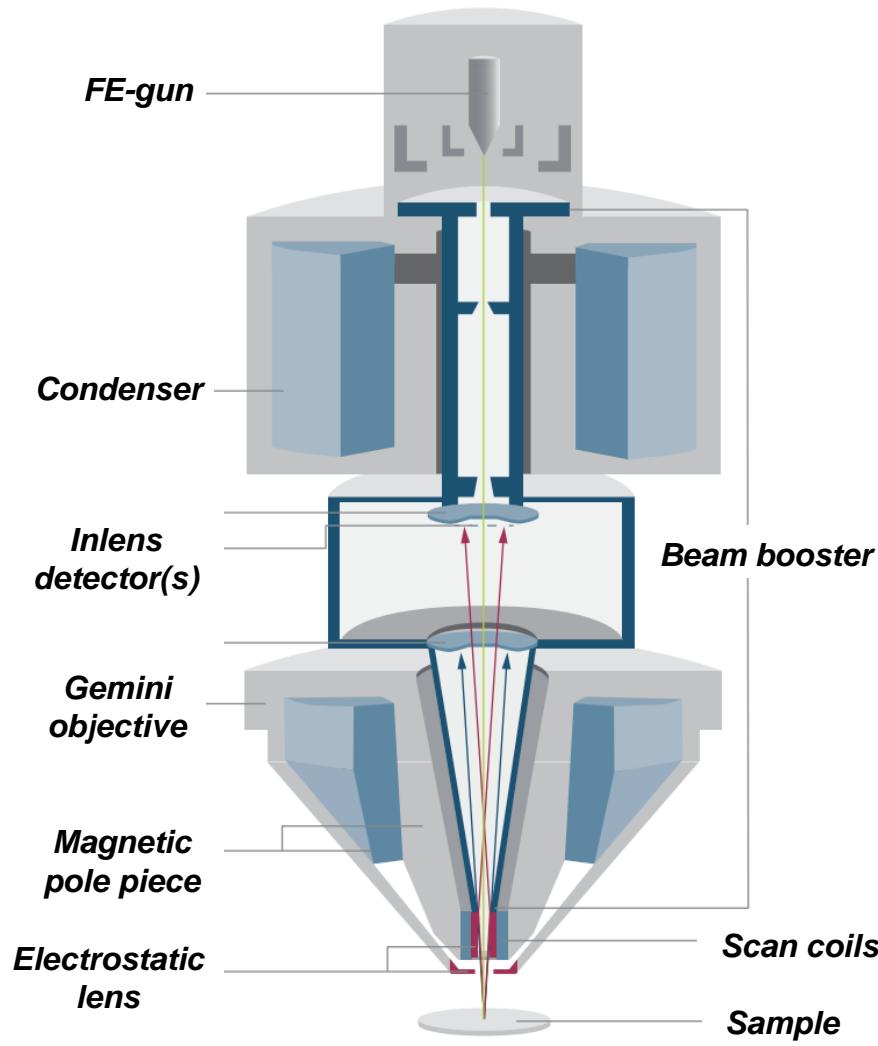


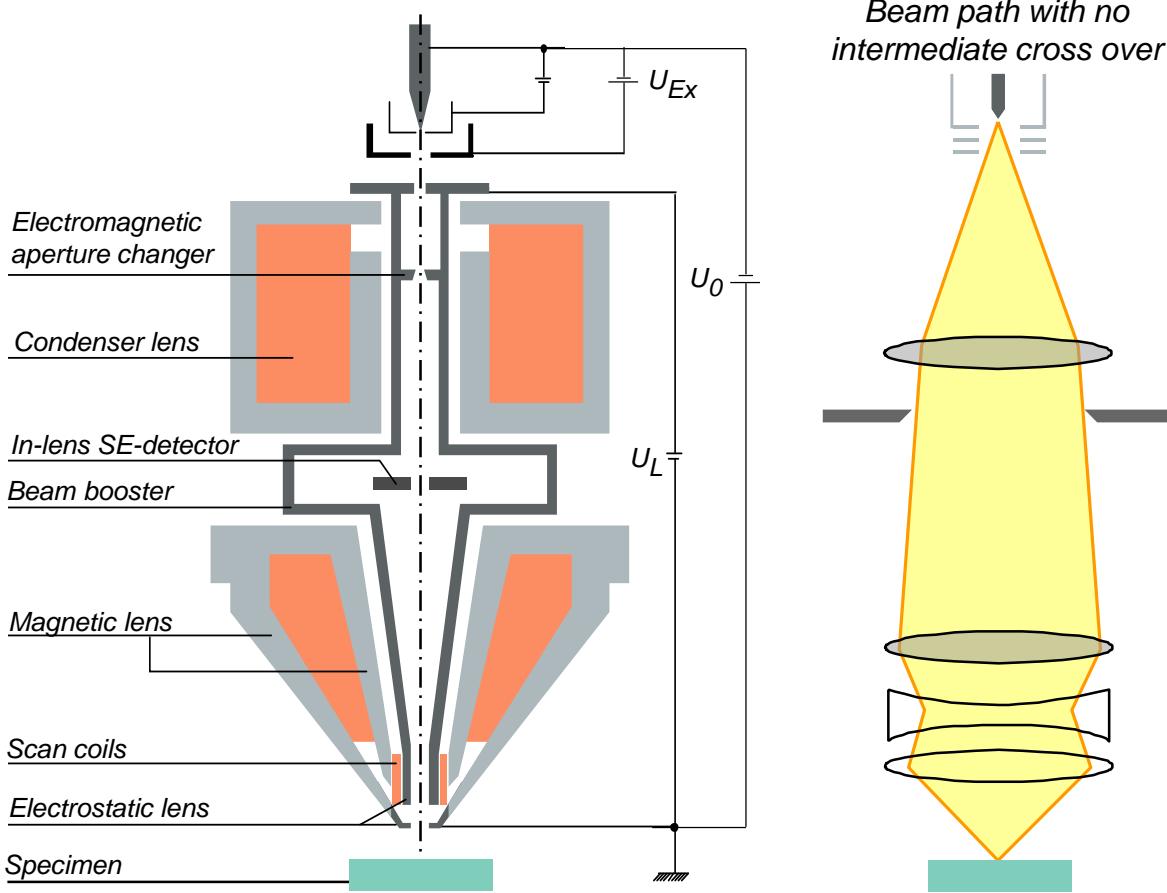
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Optics



Scanning Electron Microscope Column





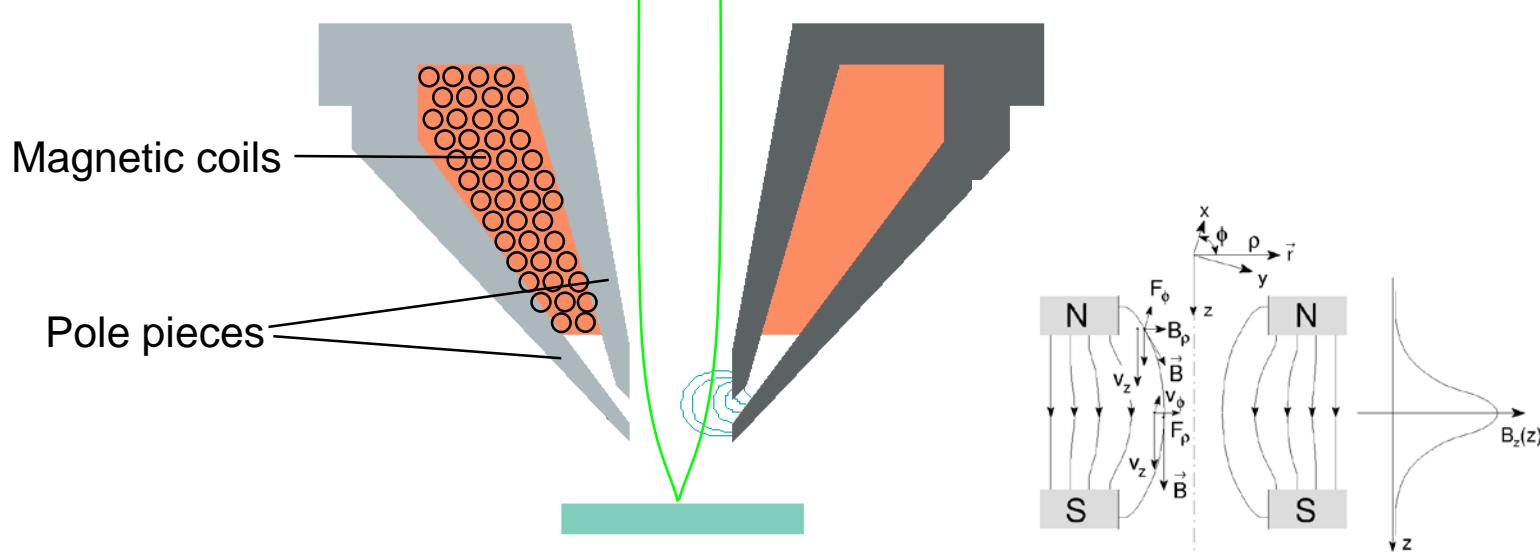
Features

- **highly stable thermal FEG**
‐ < 0.5 % /h variation
- **low beam noise**
‐ < 1 %
- **cross over free beam path**
‐ no significant Boersch effect,
‐ high depth of field
- **beam booster**
‐ superb image resolution
‐ throughout the whole
‐ beam energy range,
‐ particularly down to 100 eV.
‐ High resistance to ambient
‐ magnetic stray fields

Electromagnetic Lenses



Magnetic round lenses



Lorentz Force: $\vec{F} = -e(\vec{E} + \vec{v} \times \vec{B})$

Focal length: $f = \frac{2a}{\pi k^2}$ $k^2 = \frac{eB_0^2 a^2}{8m_0 U^*}$

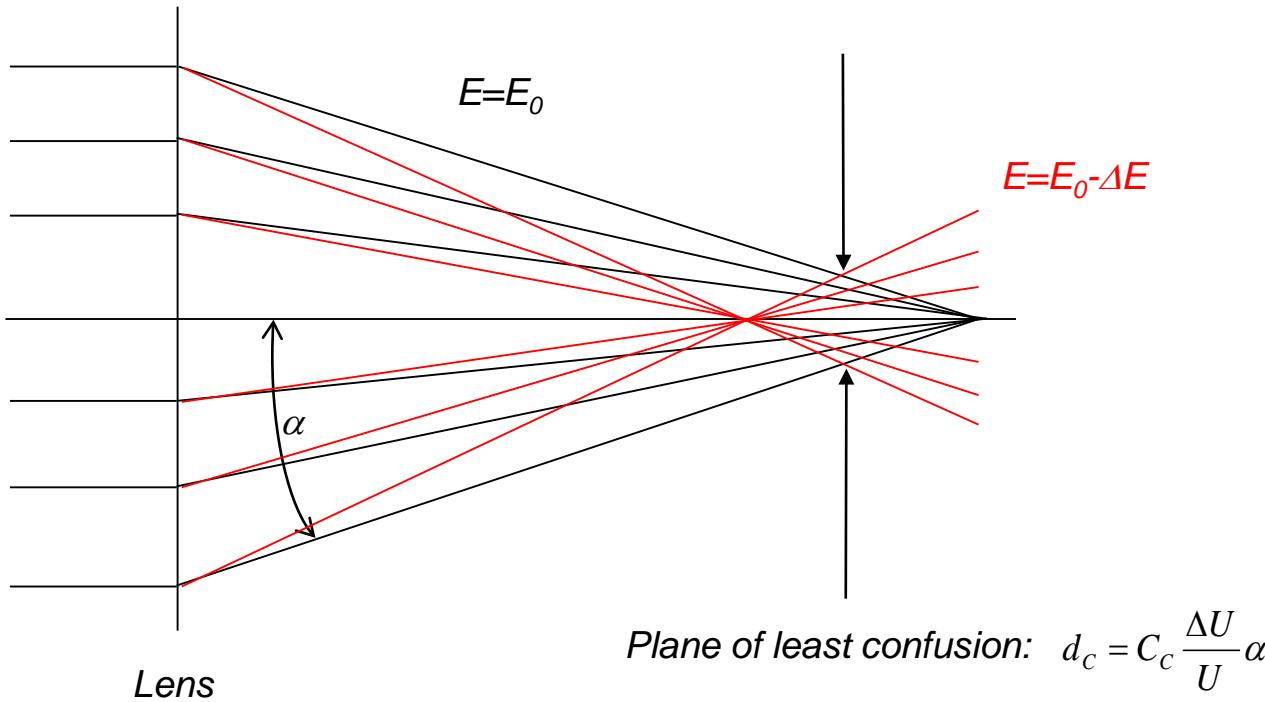
Electron Lenses: Aberrations



Chromatic aberration:

The focal length depends on the electron energy.

An energy spread of the electrons result in an aberration disc: $d_c = C_c \frac{\Delta U}{U} \alpha$

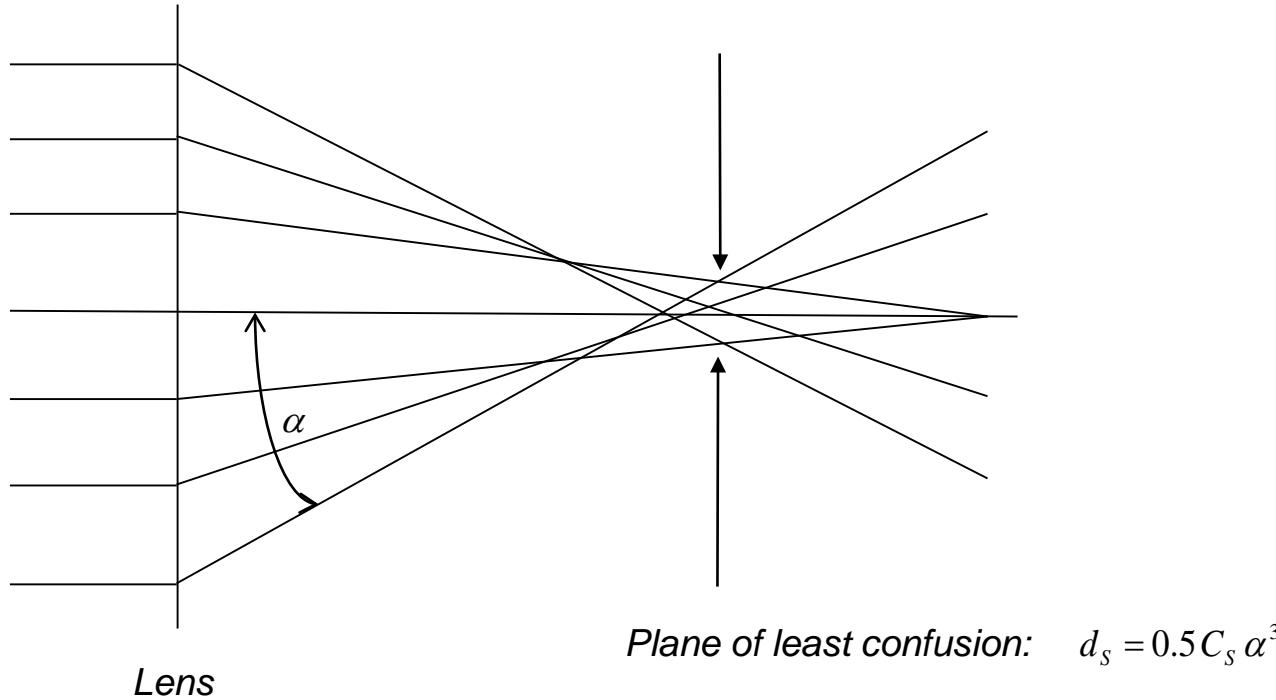


Electron Lenses: Aberrations



Spherical aberration:

Rays further from the optical axis are focussed closer to the lens resulting in an aberration disc: $d_s = 0.5 C_s \alpha^3$



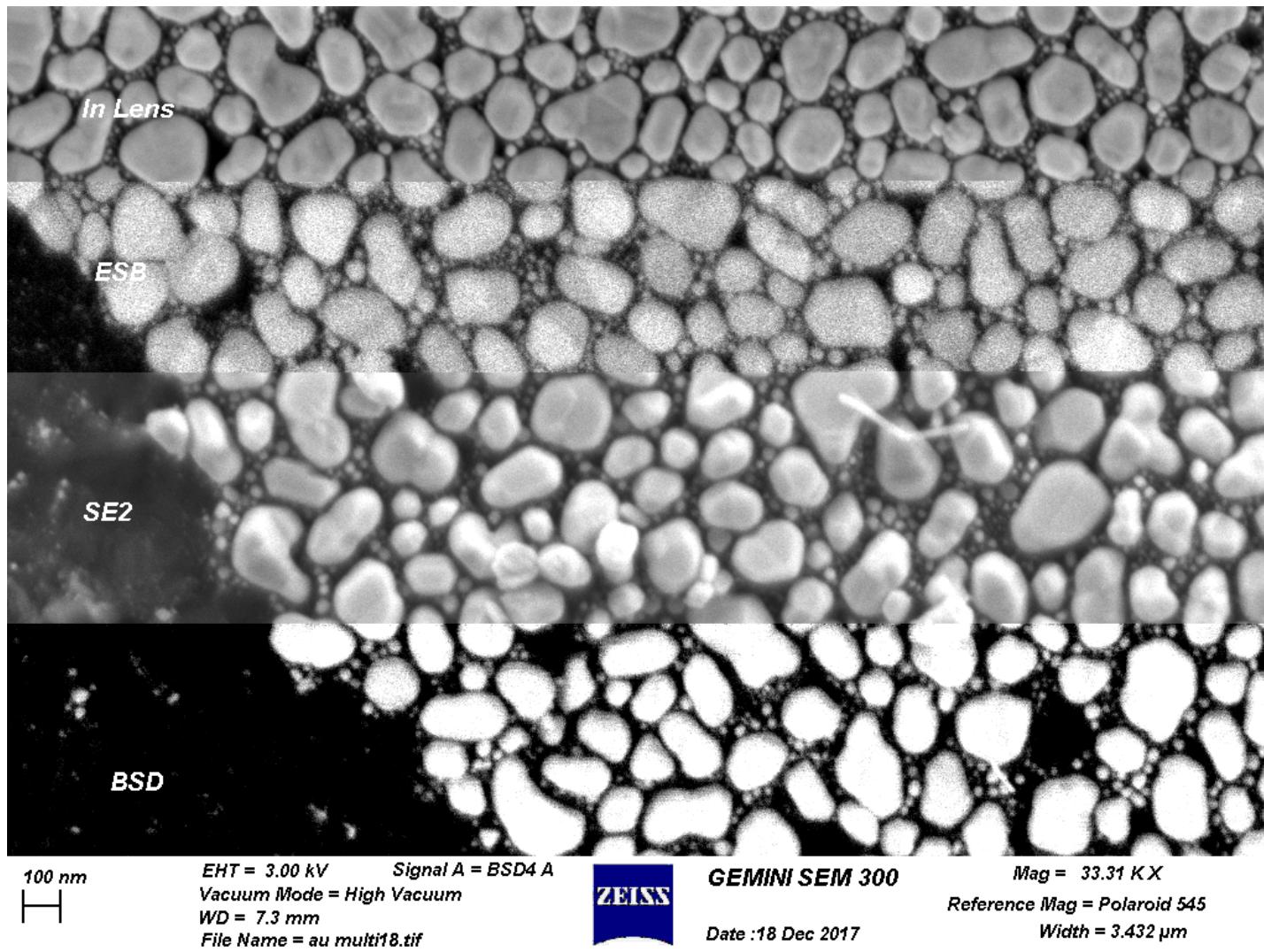
Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



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Detectors

Detector comparison

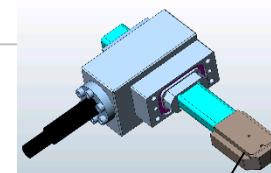


Detectors Types

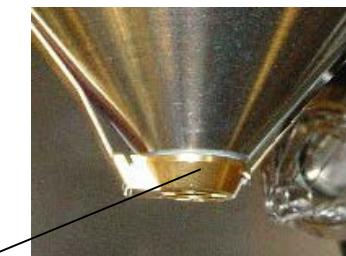
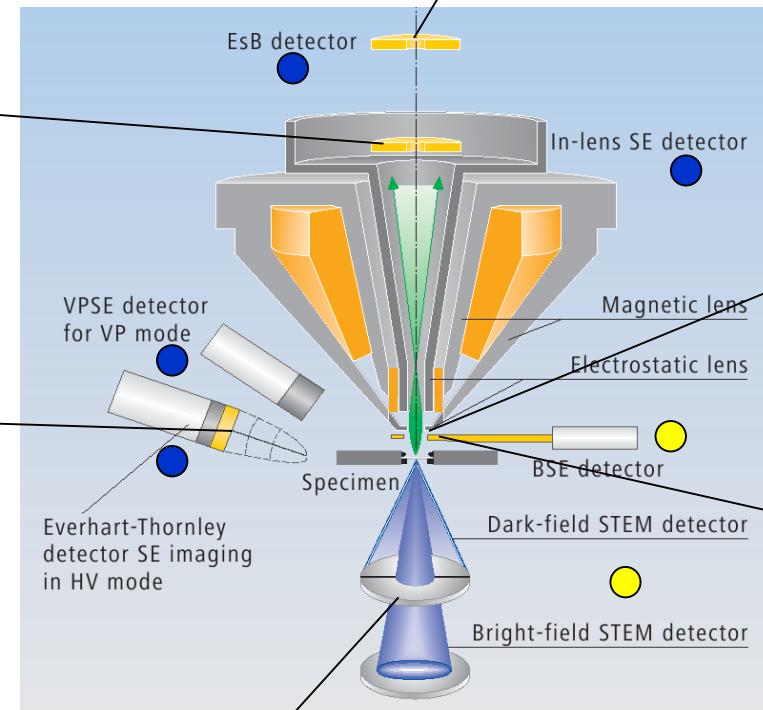
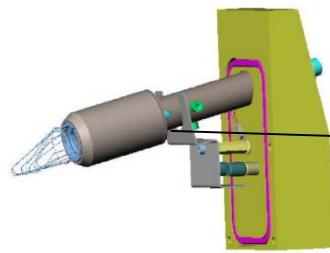


- ✓ **Secondary Electron Detector (SED)**
 - In-chamber Everhart Thornley
 - *Best for surface topography*
 - In-column (in-lens)
 - *Best for surface information (low energy)*
- ✓ **Backscattered Detector (BSE)**
 - AsB solid state (below objective lens)
 - *Best for channeling contrast (3kV and above)*
 - EsB in-column
 - *Best for Z contrast (3kV and below)*
- ✓ **Scanning Transmitted Electron Detector**
- ✓ **Variable Pressure and Extended Pressure Detectors**
 - Ionization Detectors used at 1Pa and below
 - ✓ Energy Dispersive Spectrometer (EDS)
 - ✓ Wavelength Dispersive Spectrometer (WDS)
 - ✓ Cathodoluminescence Detector (CL)
 - ✓ Electron Backscattered Diffraction Pattern (EBSD or EBSP)

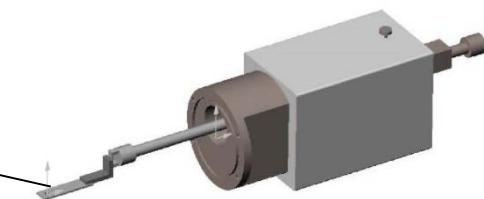
Various Electron Detectors



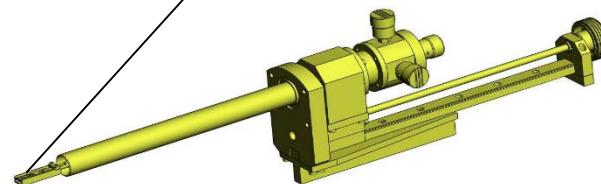
Energy selective Backscatter detector (EsB)



Angle selective Backscatter detector (AsB)



Retractable BSE Detector



- Scintillator Detector
- Semiconductor Detector

When to use which detector



Detector	Information	Opt.Working Distance	Best Energy
Everhart-Thornley	Topographic surface information	5-12mm	0.02-30kV
InLens	Surface details, High Resolution Imaging	<5mm	0.02-5kV
AsB or SSBSE	Z-Contrast Channeling contrast (crystallographic information, strain, deformation)	5-10mm 2-5mm (material dependent)	>5kV
EsB	Z-Contrast (sharp due to energy filter) Low Loss BSE: Compositions, Bondings	<5mm	<1.5 kV

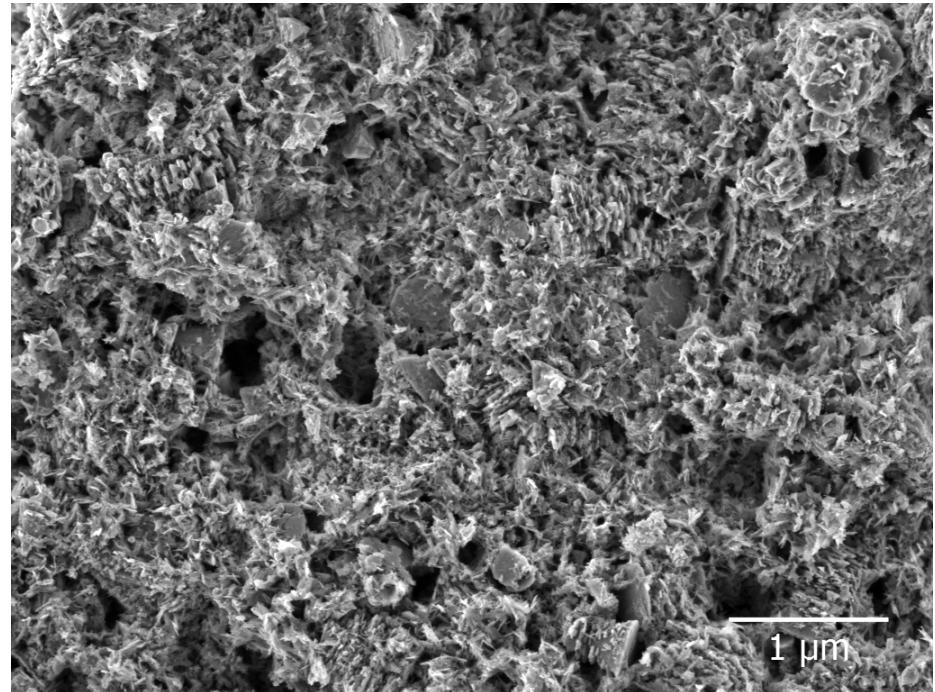
Scanning Electron Microscopy and Energy-Dispersive X-Ray Spectroscopy



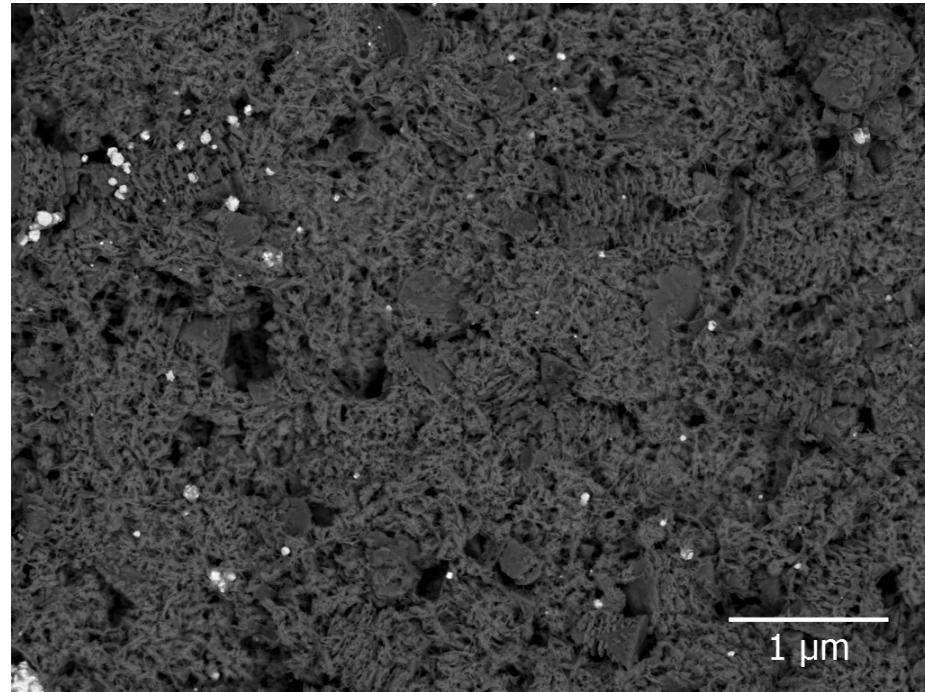
Facilities Days Open House 2018

Applications

Pt Nanoparticles on Nonconductive Al₂O₃ matrix.

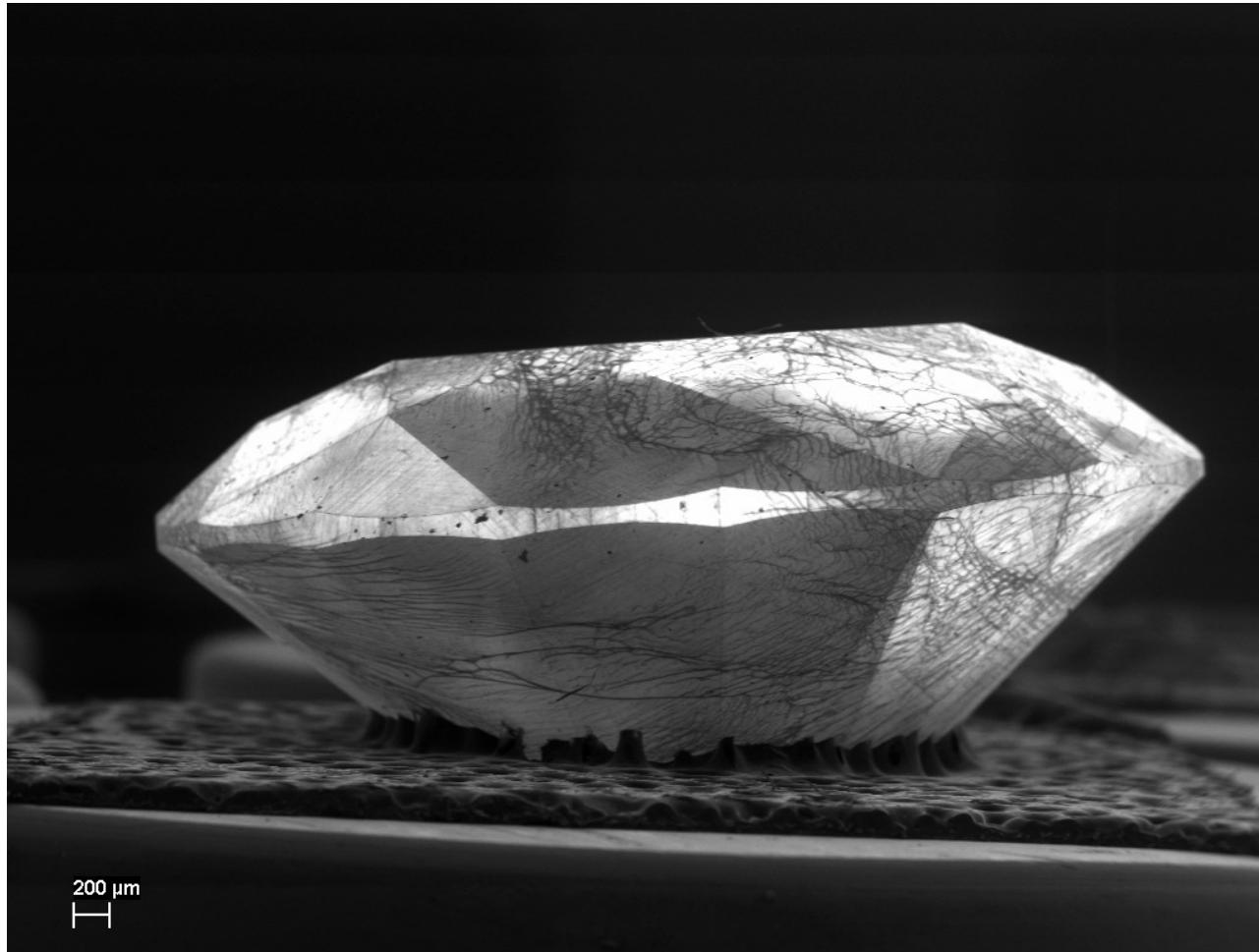


Inlens SE, 1 kV

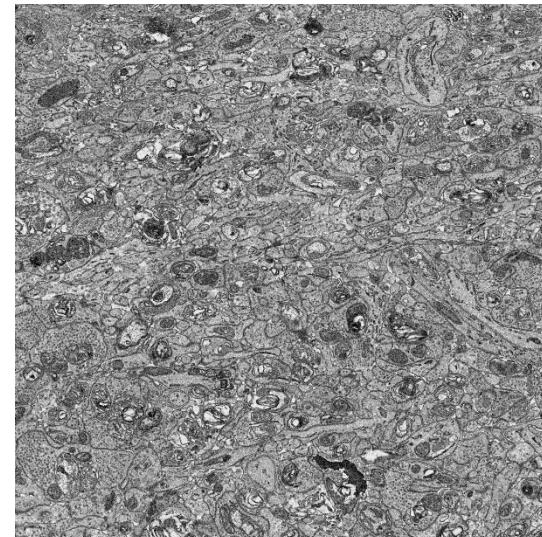
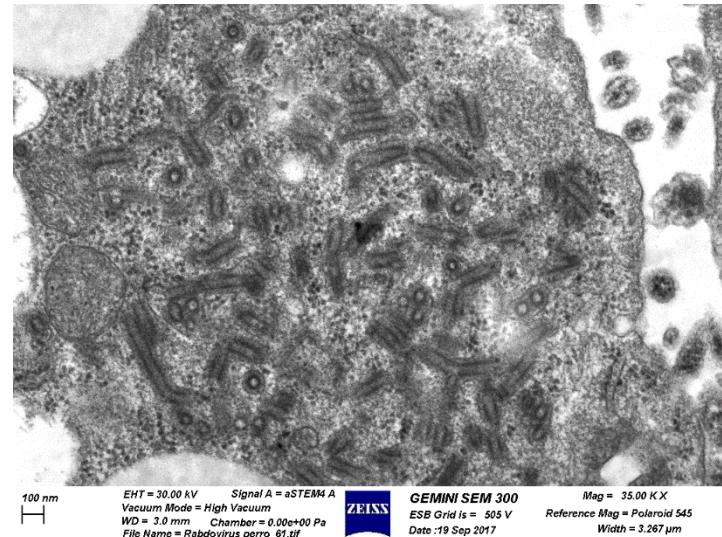
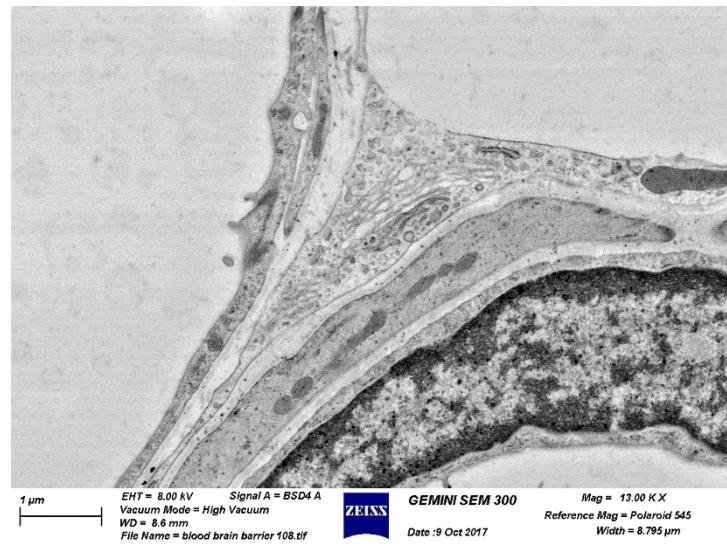
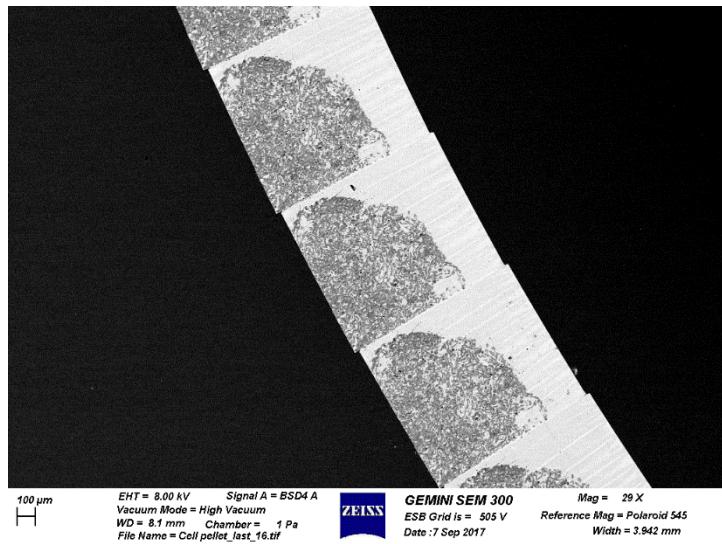


ESB1 kV

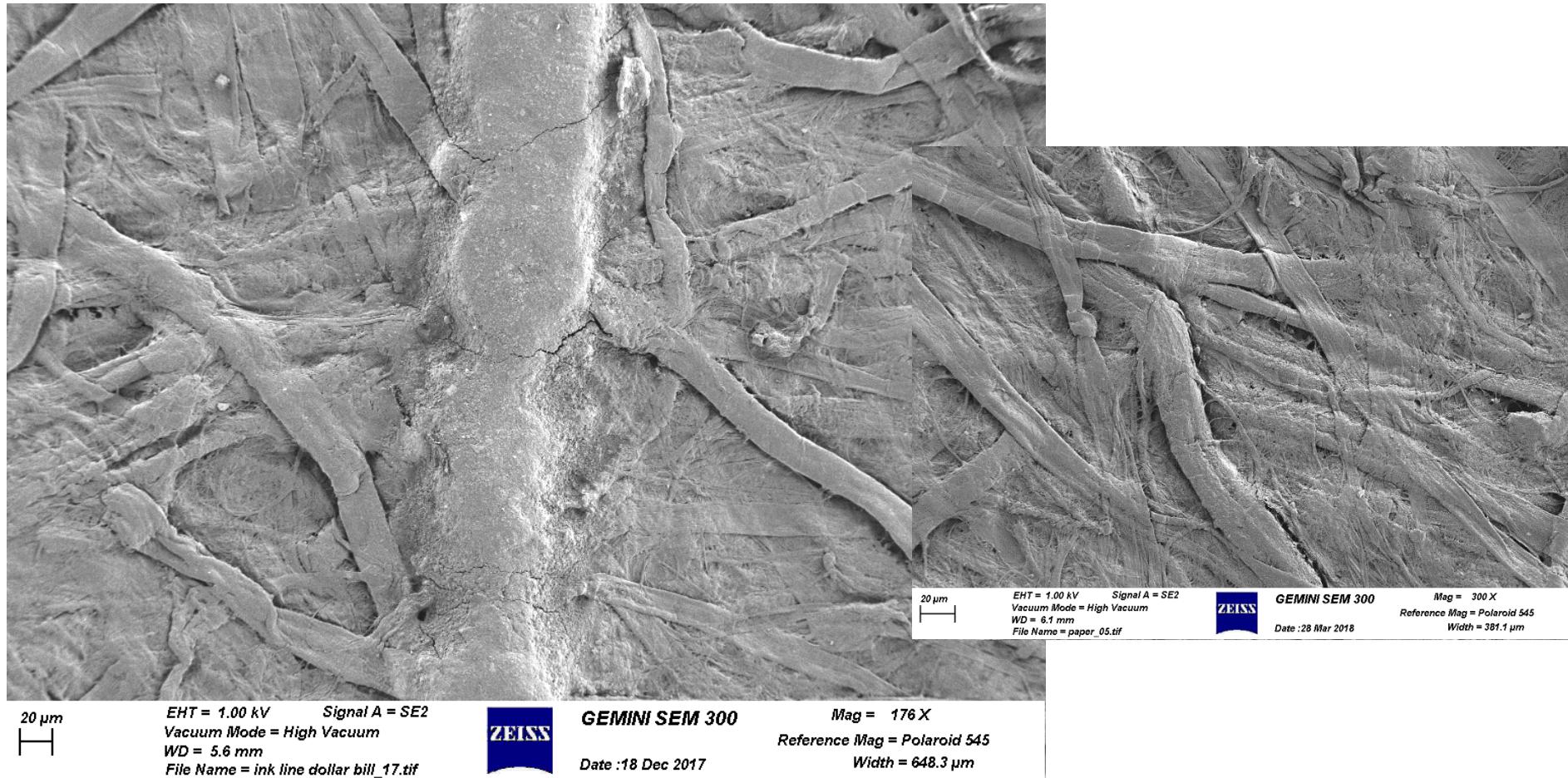
VP CL image showing dislocations



Bio applications with BSD



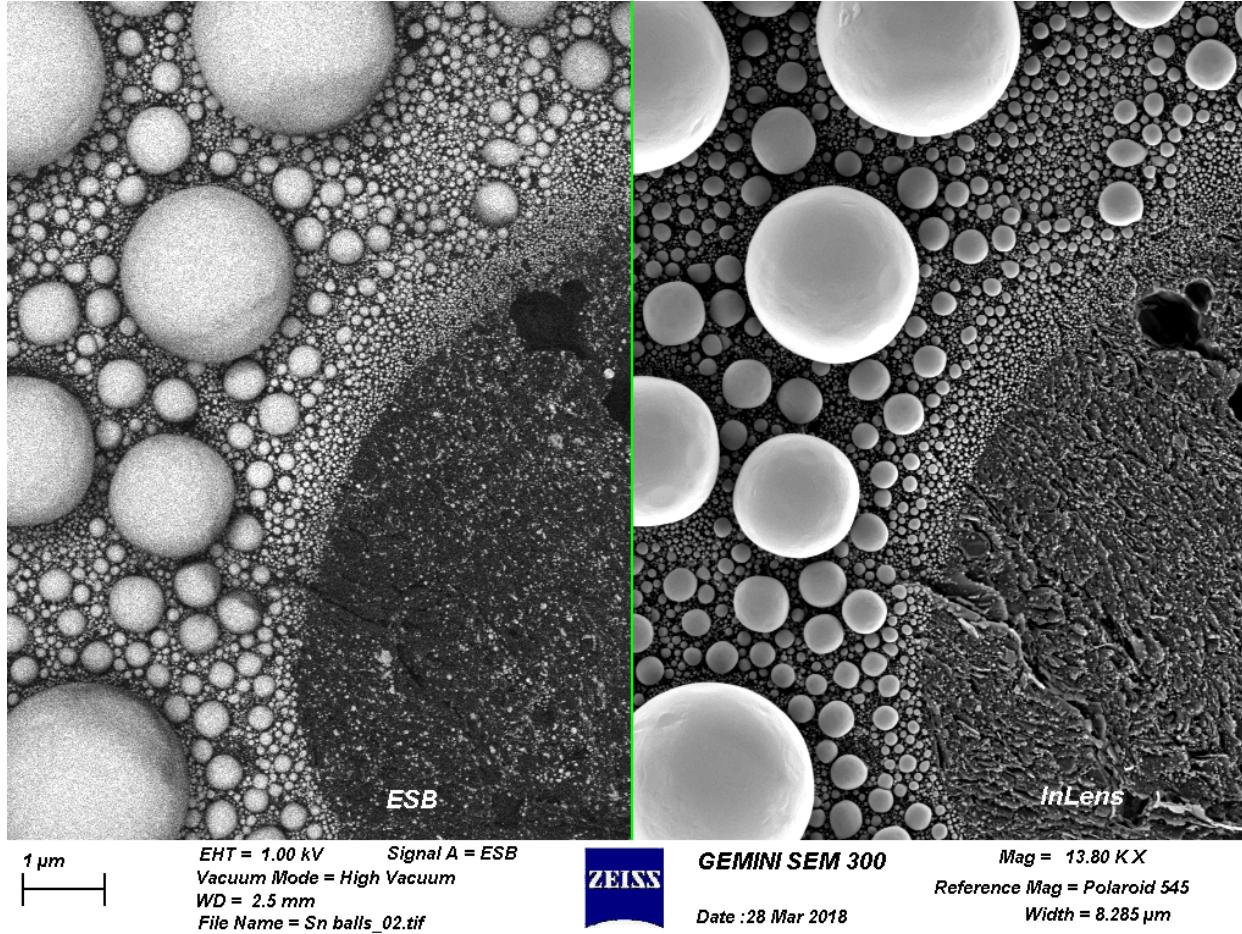
Low kV Imaging Ink line on paper



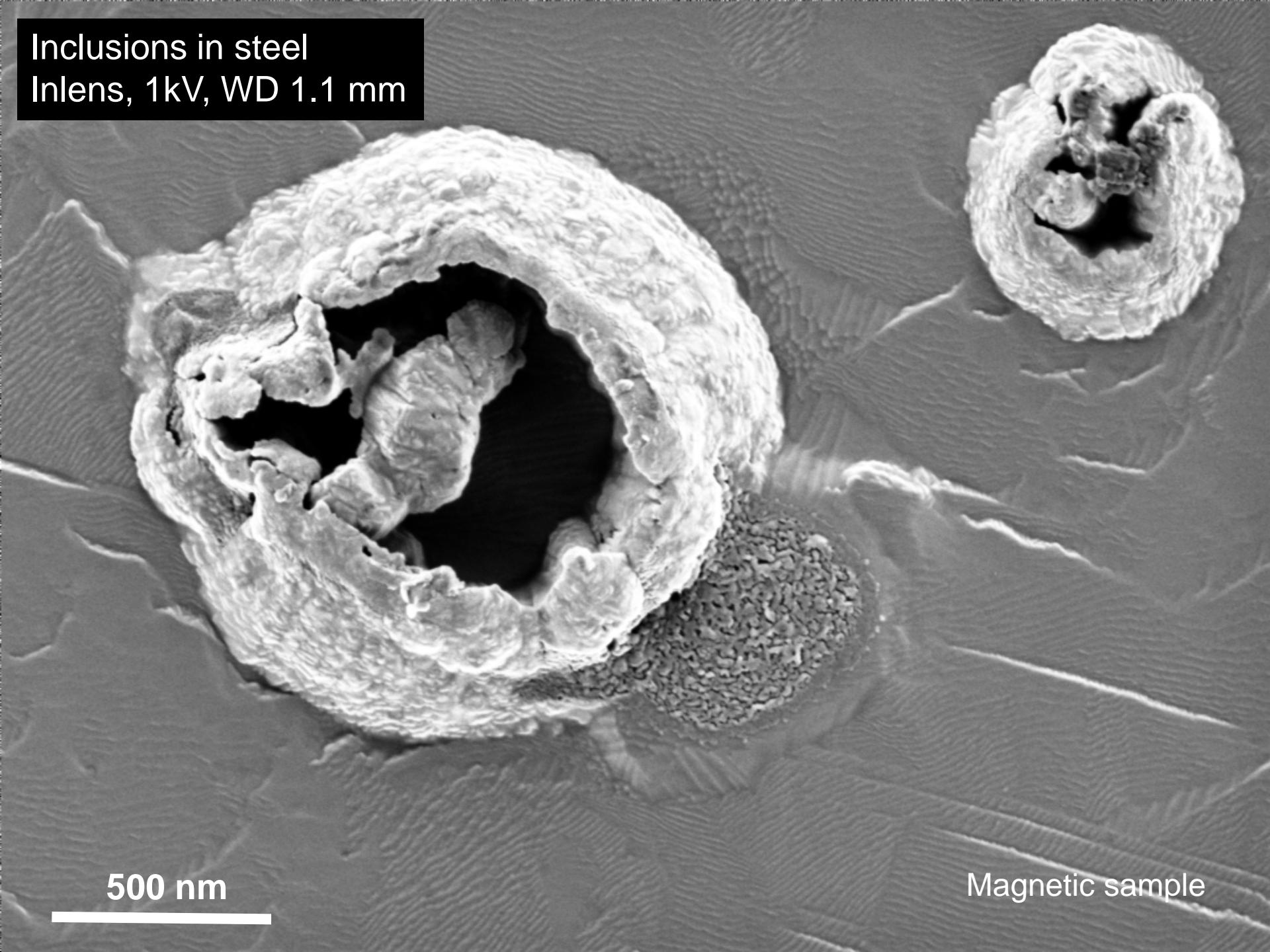
Tin balls



High resolution sample



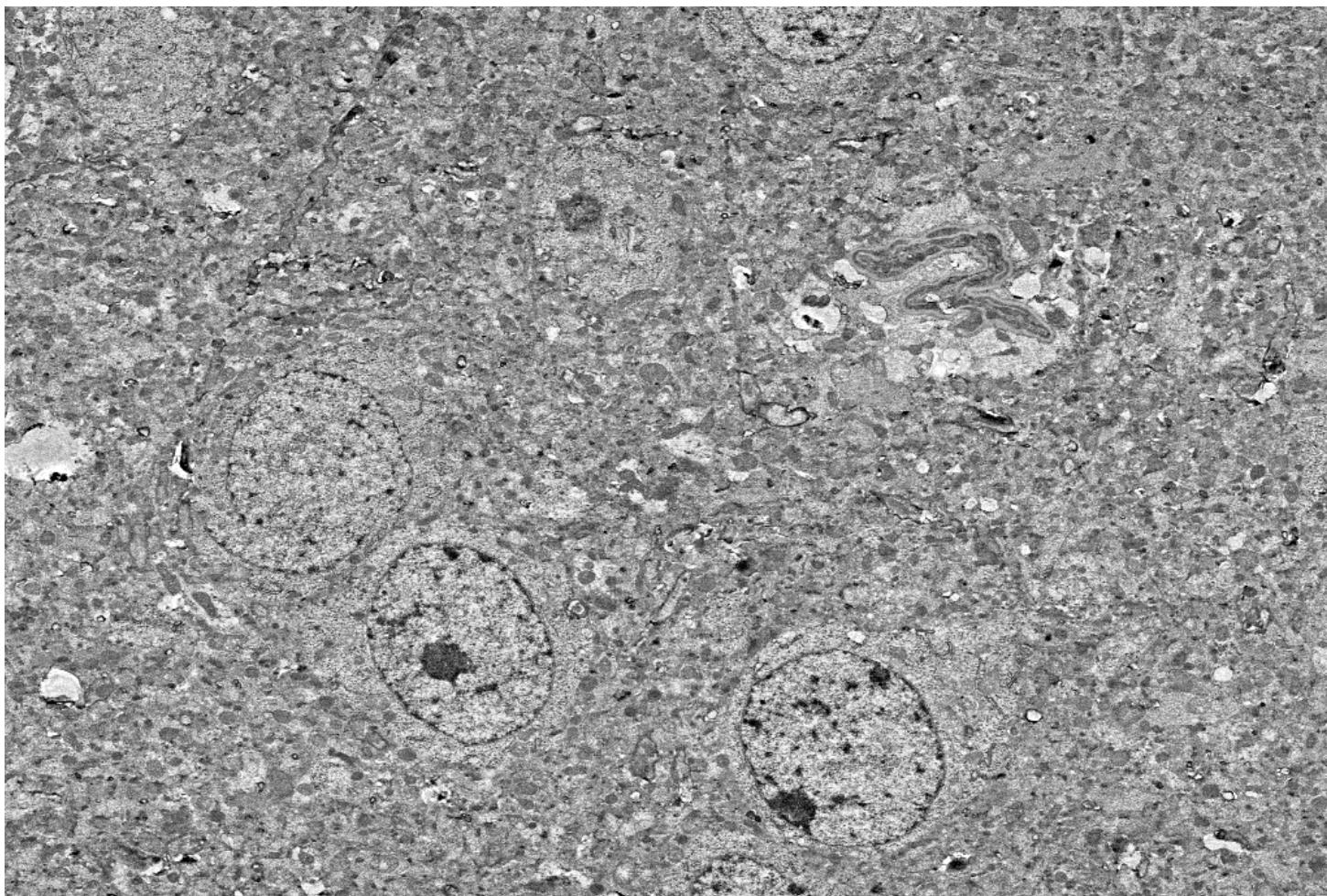
Inclusions in steel
Inlens, 1kV, WD 1.1 mm



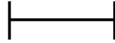
500 nm

Magnetic sample

Using SEM to mimic TEM



3 μ m



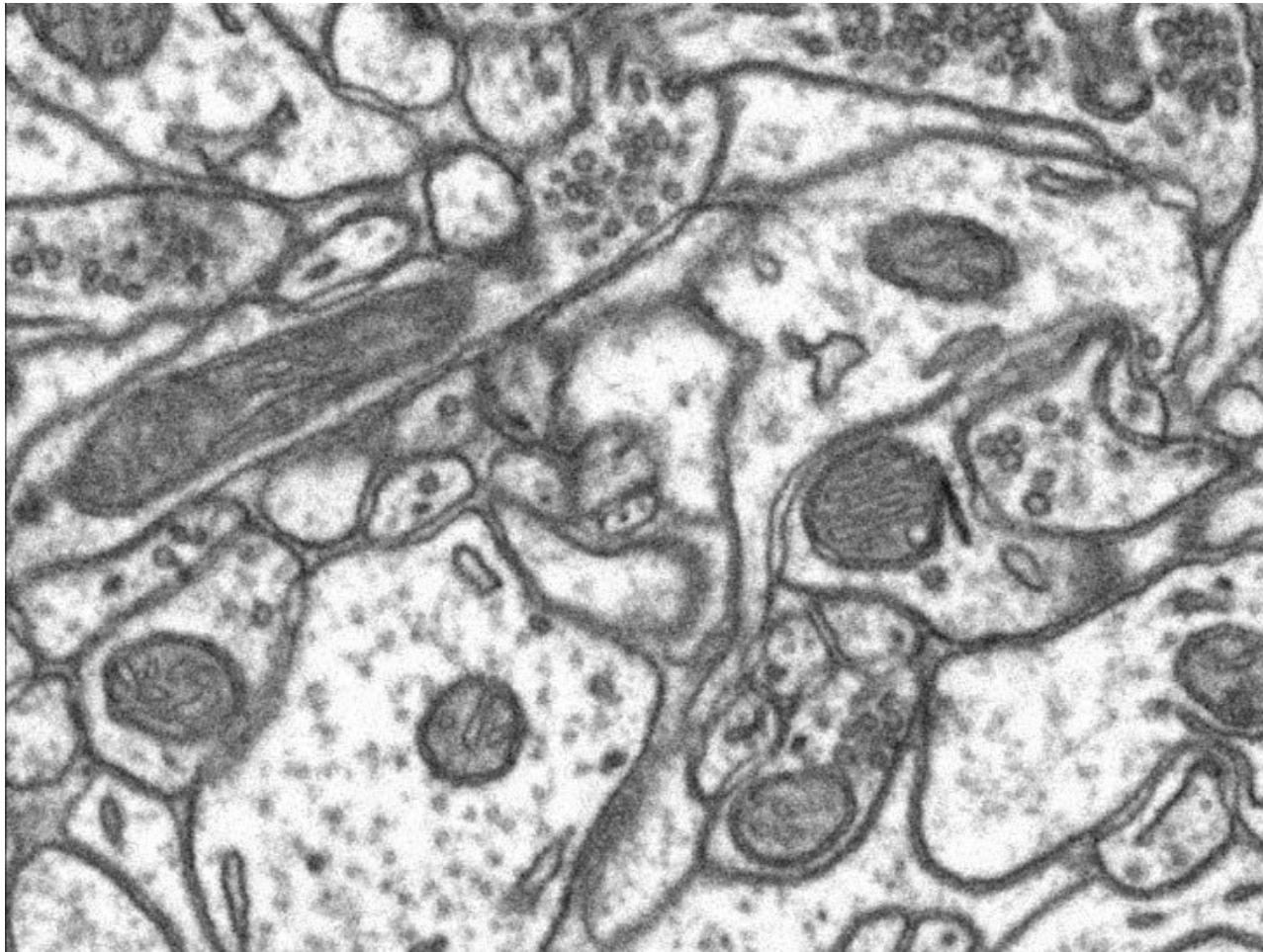
EHT = 8.00 kV Signal A = BSD4 A
Vacuum Mode = High Vacuum
WD = 7.5 mm
File Name = Coverslip 1123_07.tif



GEMINI SEM 300
Pixel Size = 40.60 nm
Date : 15 Mar 2018

Mag = 2.75 KX
Reference Mag = Polaroid 545
Width = 41.57 μ m

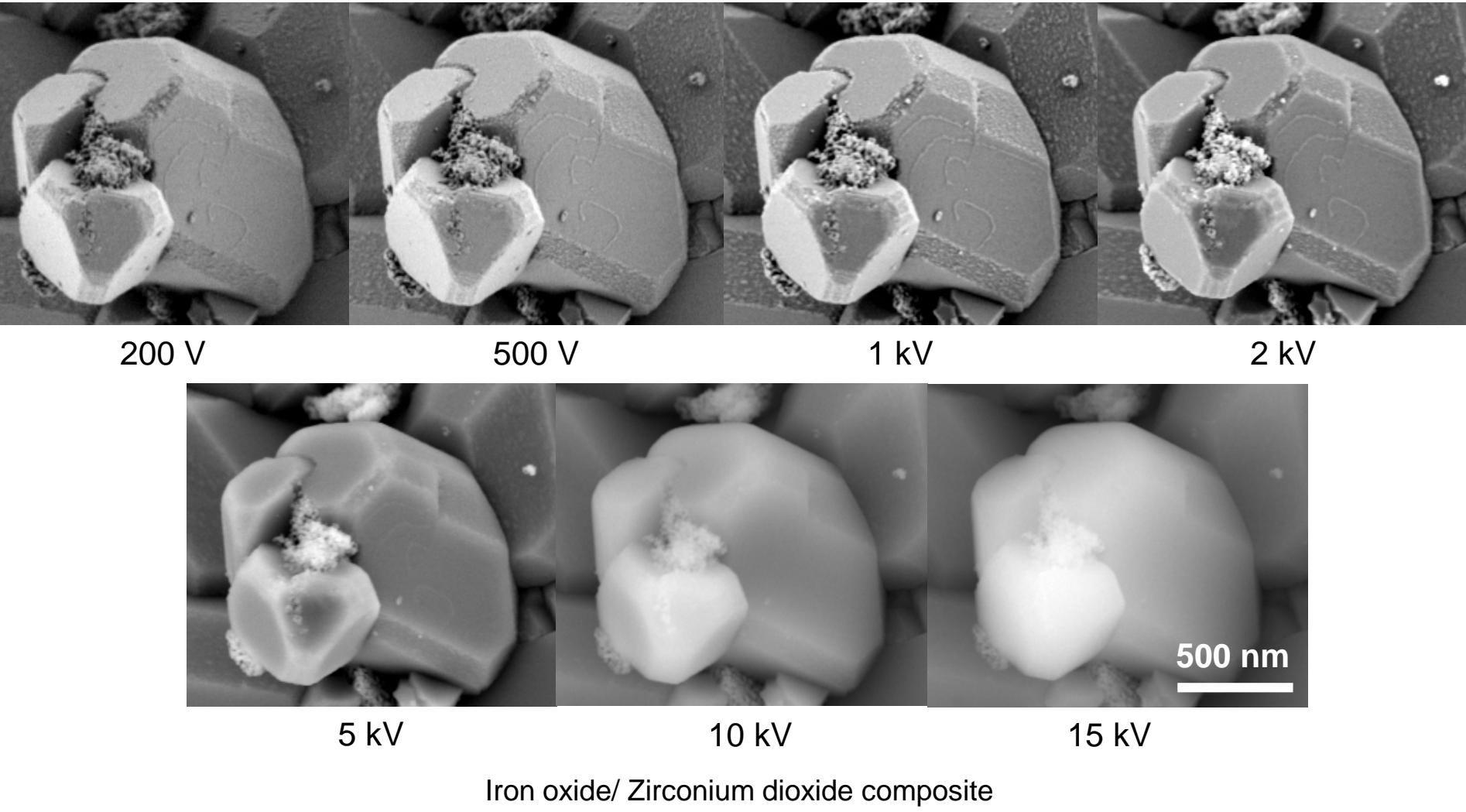
Brain Tissue - Low Voltage EsB Imaging



Courtesy Marco Cantoni EPFL Lausanne

Why low-kV imaging?

More surface sensitivity

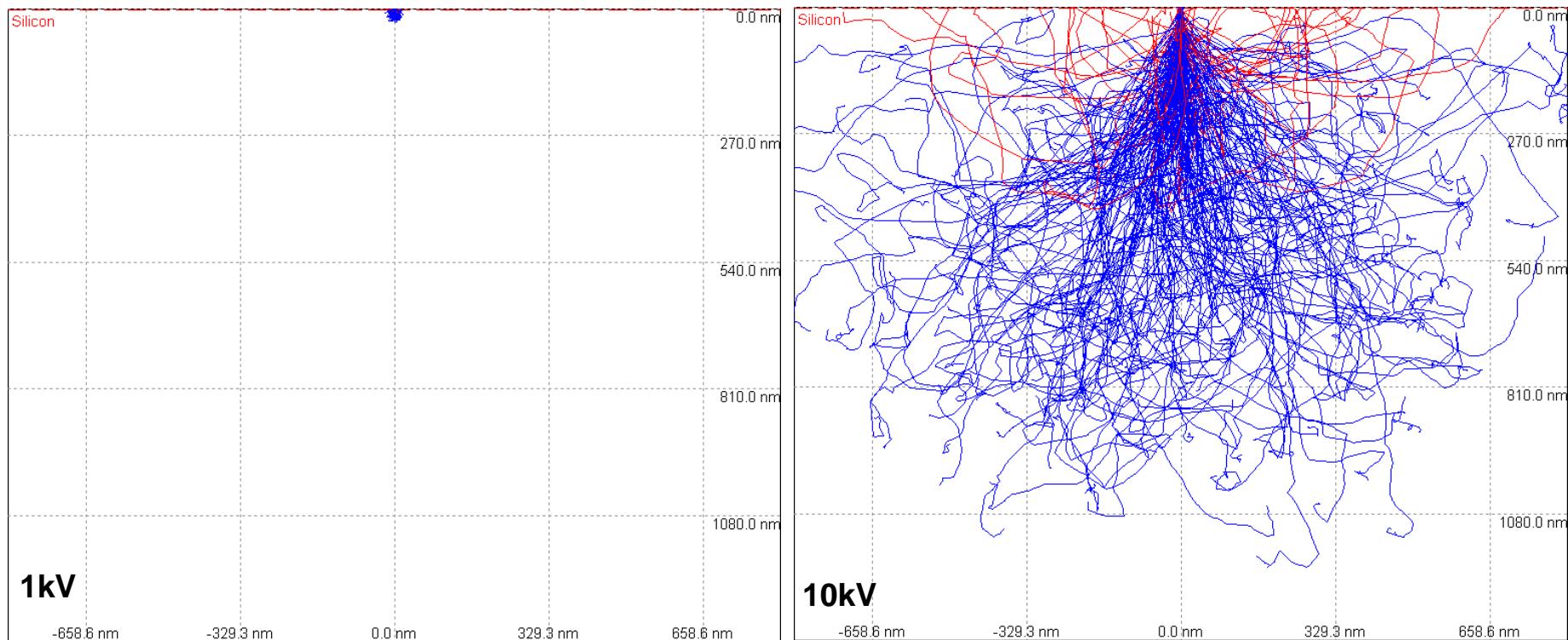


Iron oxide/ Zirconium dioxide composite

Beam Sample Interaction – Influence of Beam Energy

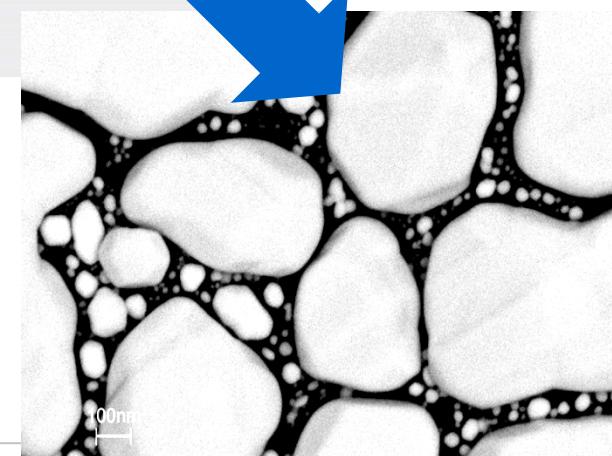
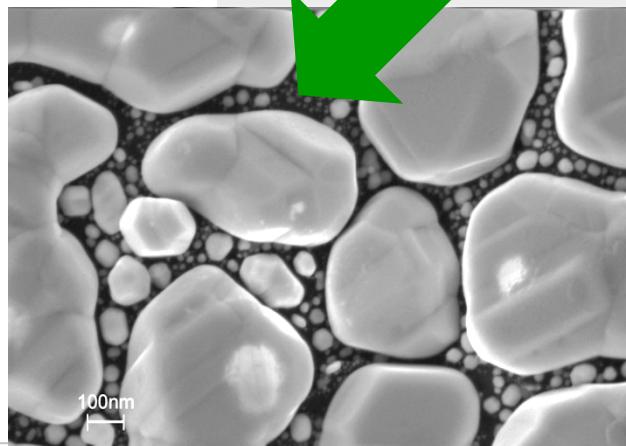
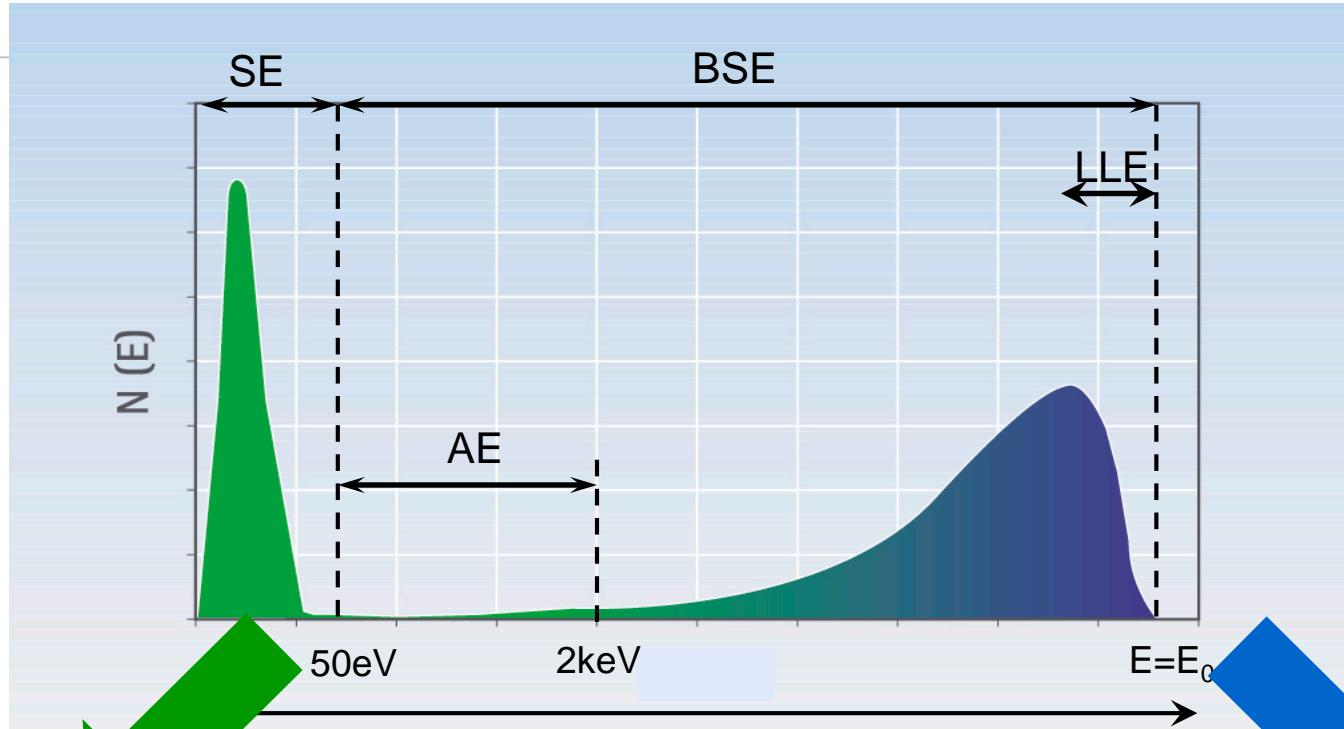


Monte Carlo Simulations



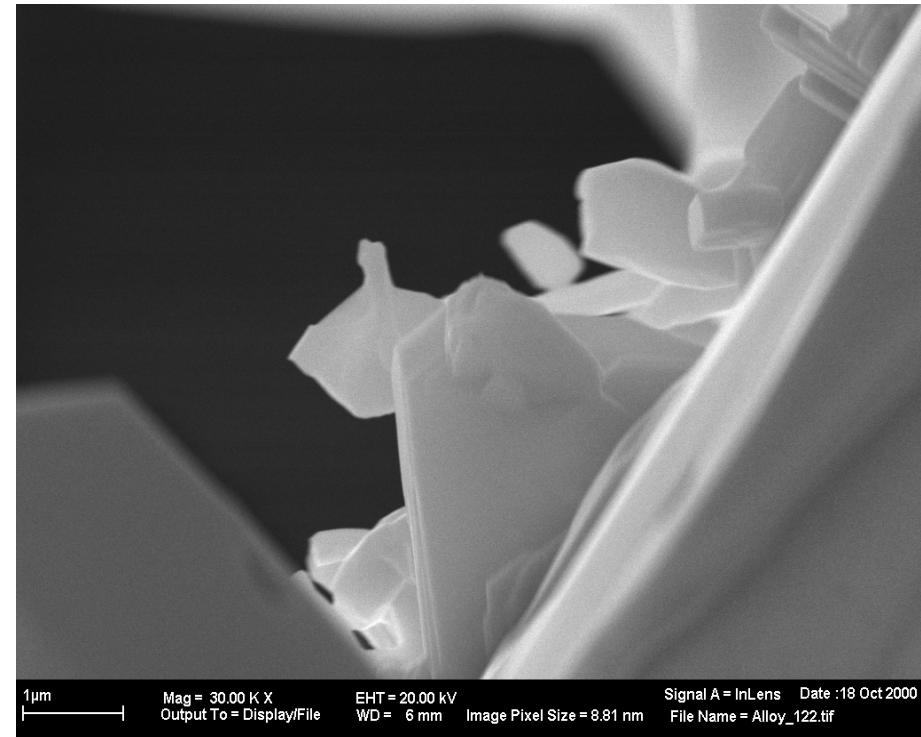
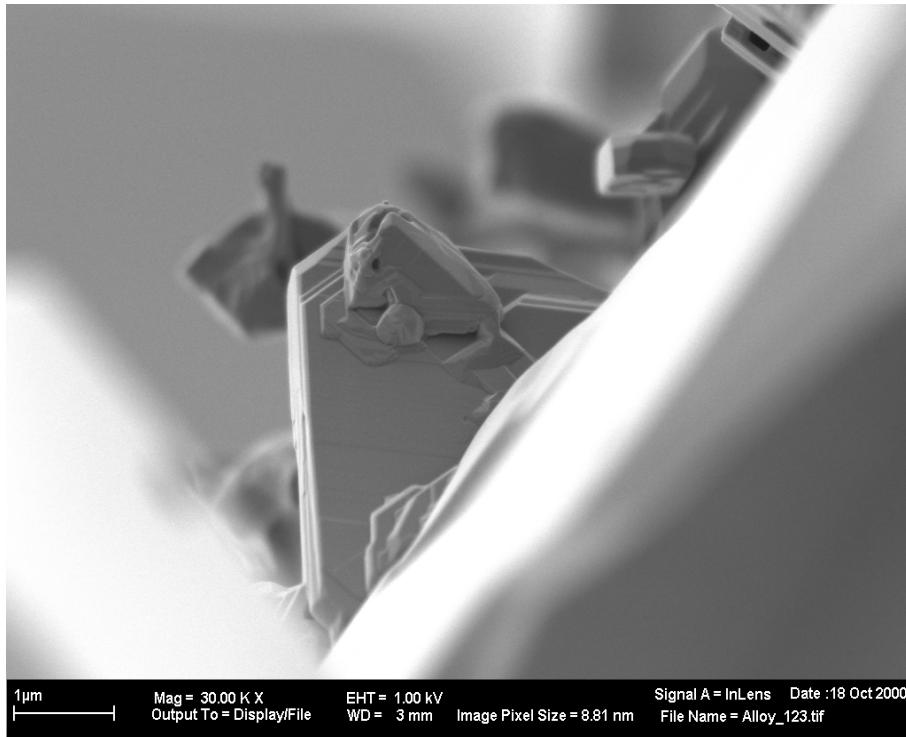
Monte Carlo simulation of the beam – sample interaction for a Si sample at 1kV and 10kV.

Beam Sample Interaction



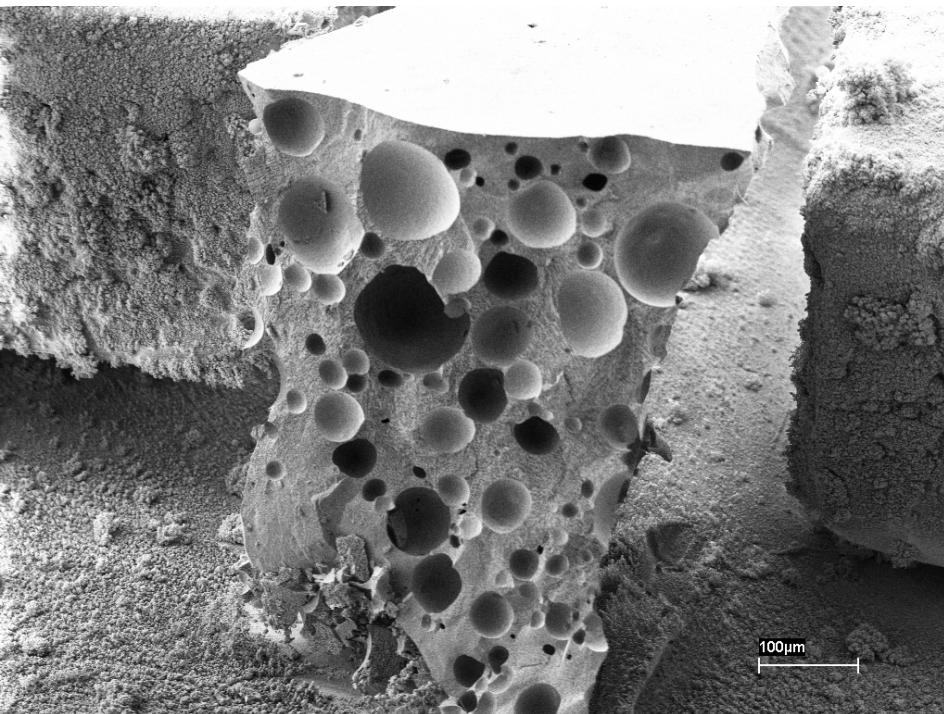
Target is to separate information

Beam Sample Interaction – Influence of Beam Energy

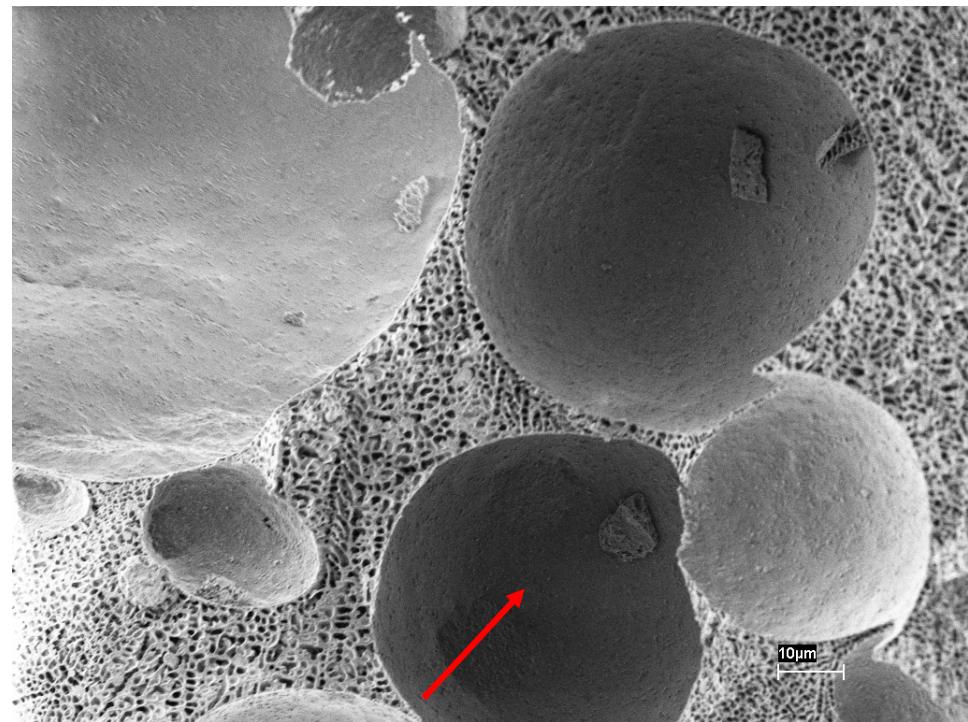


Platinum Rhodium Alloy Crystals at 1kV (left) and at 20kV (right)

Cryo SEM Applications

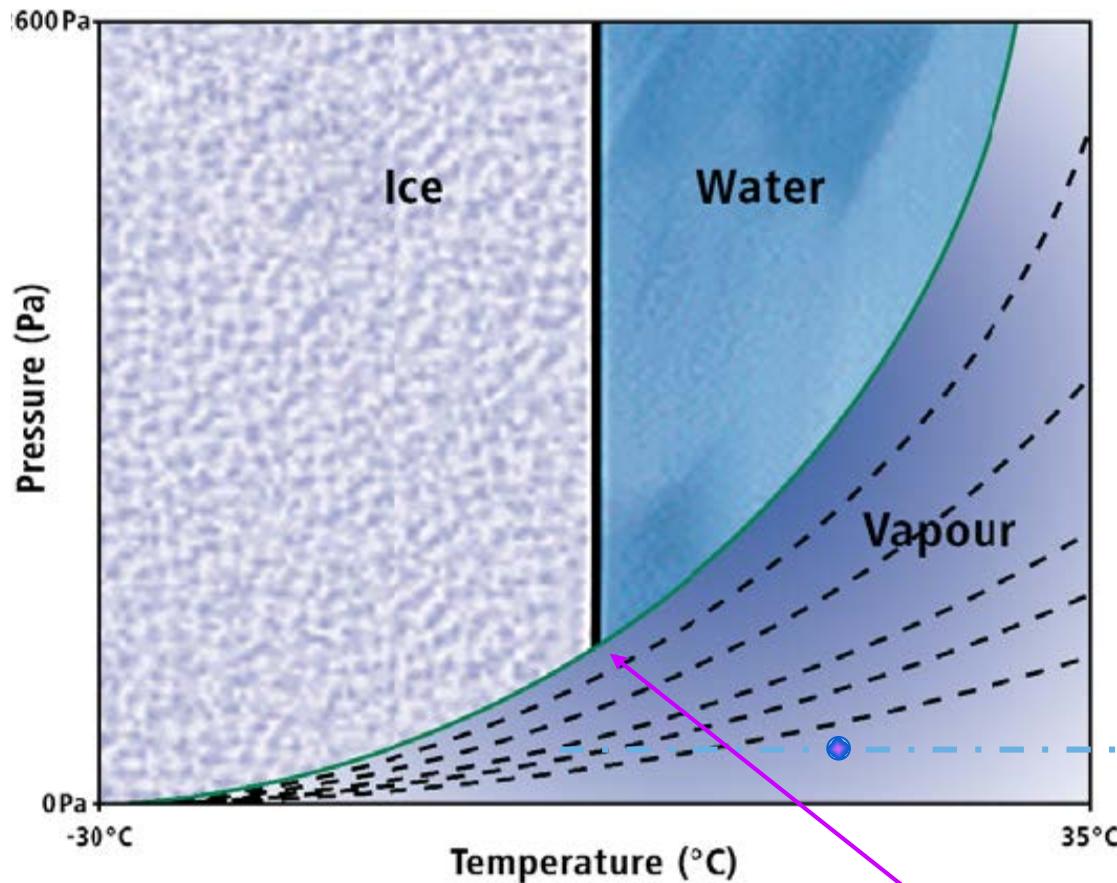


*Freeze fracture,
(Temp. -130°C)*



*Fracture at the interface Fat - Water
fat droplets*

Water Phase Diagram



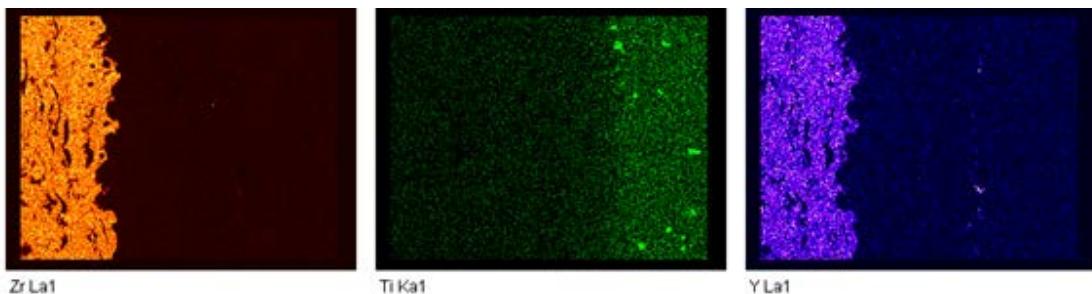
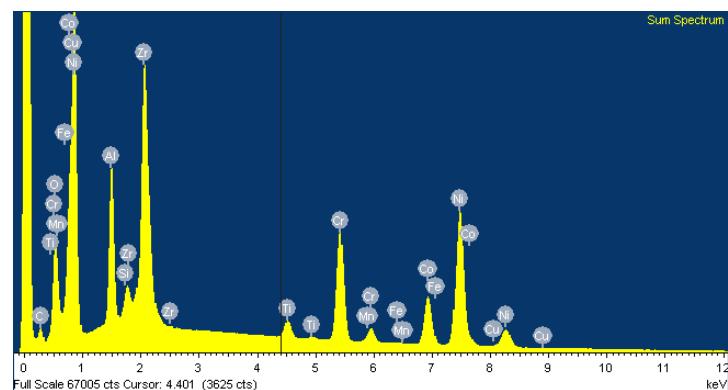
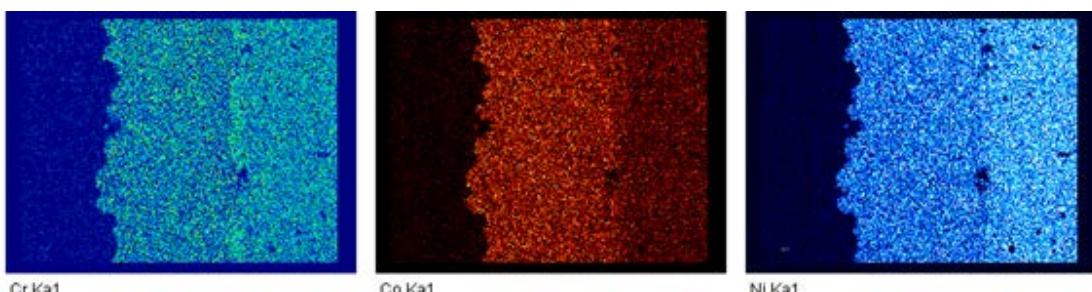
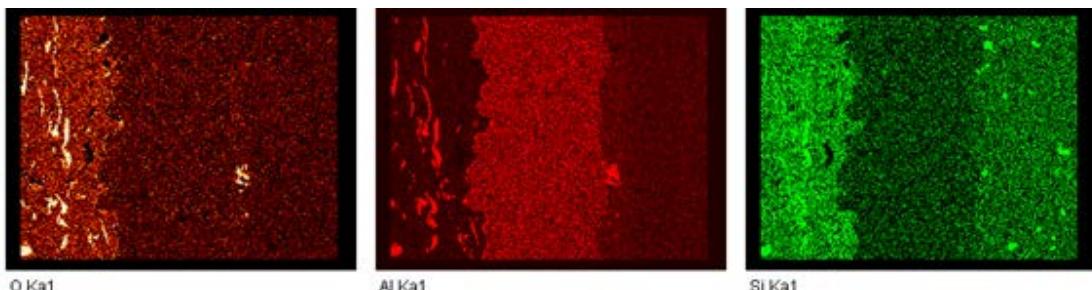
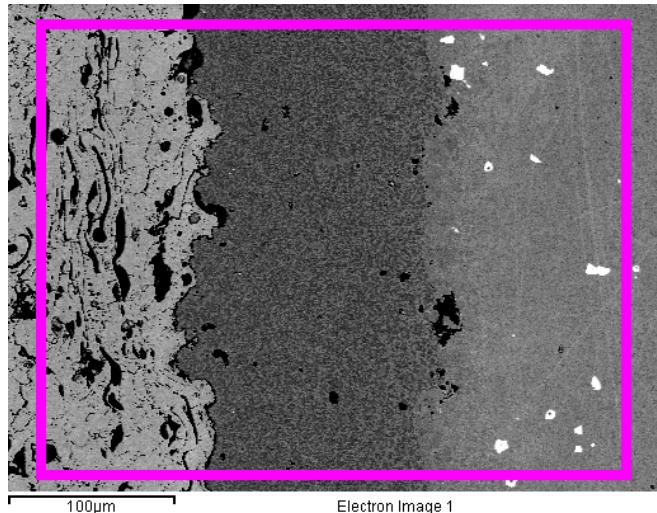
600 Pa - 750 Pa
Imaging liquid water; the specimen is cooled to just above 0 °C (The water vapour pressure in the microscope is minimised).

650 Pa – 3000 Pa
Imaging of liquid water close to room temperature; High water vapour pressure required to prevent dehydration and maintaining the structure of sensitive samples such as Fauna and Flora.

Triple point
0°C, 612 Pa (4.6 Torr)

Cryo-Technology

EDS Analysis – Turbine Blades



EDS Analysis at 15kV with charge compensation.

Energy-Dispersive X-Ray Spectroscopy



Energy-dispersive X-ray spectroscopy (EDS, EDX, EDXS or XEDS), sometimes called **energy dispersive X-ray analysis (EDXA)** or **energy dispersive X-ray microanalysis (EDXMA)**, is an analytical technique used for elemental analysis.

EDS relies on the principle that all elements have unique atomic structures which are represented by unique peaks on their electromagnetic spectra.

To stimulate the emission of characteristic X-rays from a specimen, a high-energy electron beam is focused into the sample.

The incident beam may excite an electron in an inner shell, ejecting it from the shell while creating an electron hole where the electron was.

An electron from an outer, higher-energy shell then fills the hole, and the difference in energy between the higher-energy shell and the lower energy shell may be released in the form of an X-ray.

The number and energy of the X-rays emitted from a specimen can be measured by an energy-dispersive spectrometer.

As the energies of the X-rays are characteristic of the difference in energy between the two shells and of the atomic structure of the emitting element, EDS allows the elemental composition of the specimen to be measured.

Inelastic Collision Summary

X-Ray Generation

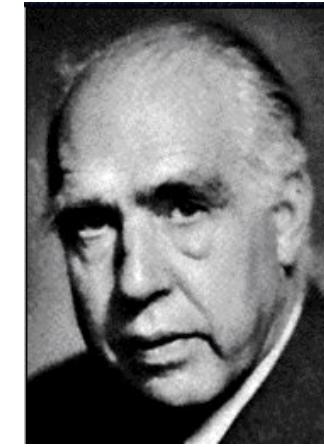
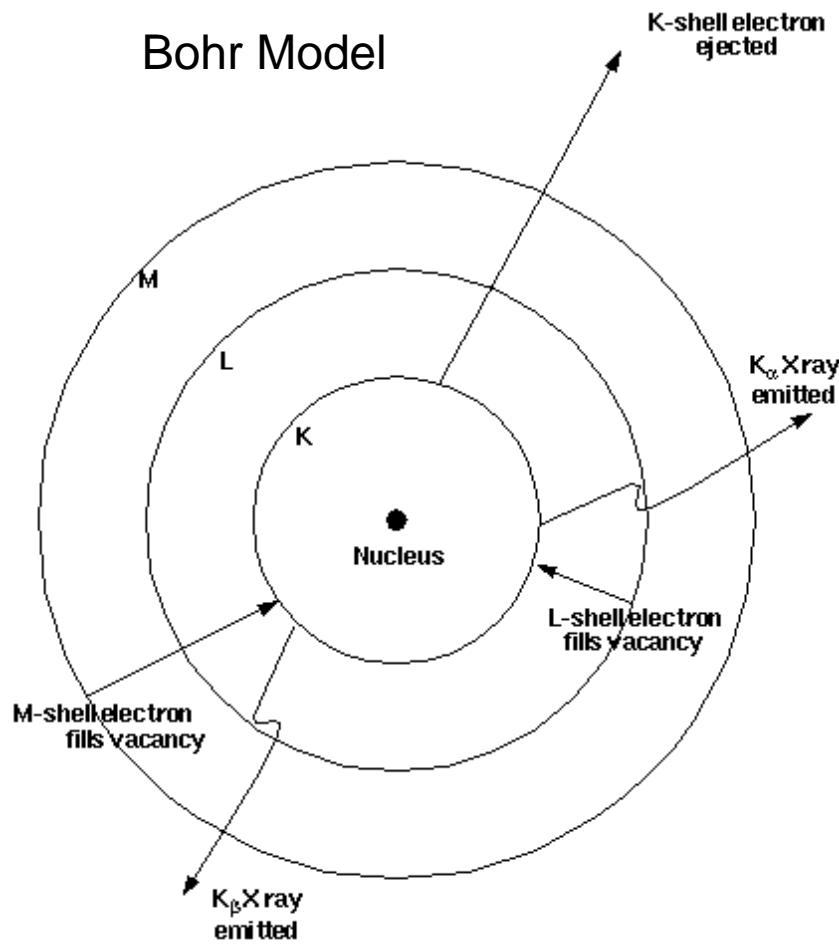


Primary beam electron interacts with atom
There is an energy transfer

An electron from the atom is liberated
Creates a secondary electron (SE)

SE has low energy
The atom is excited and wants to return to a relaxed state
Characteristic X-ray is emitted

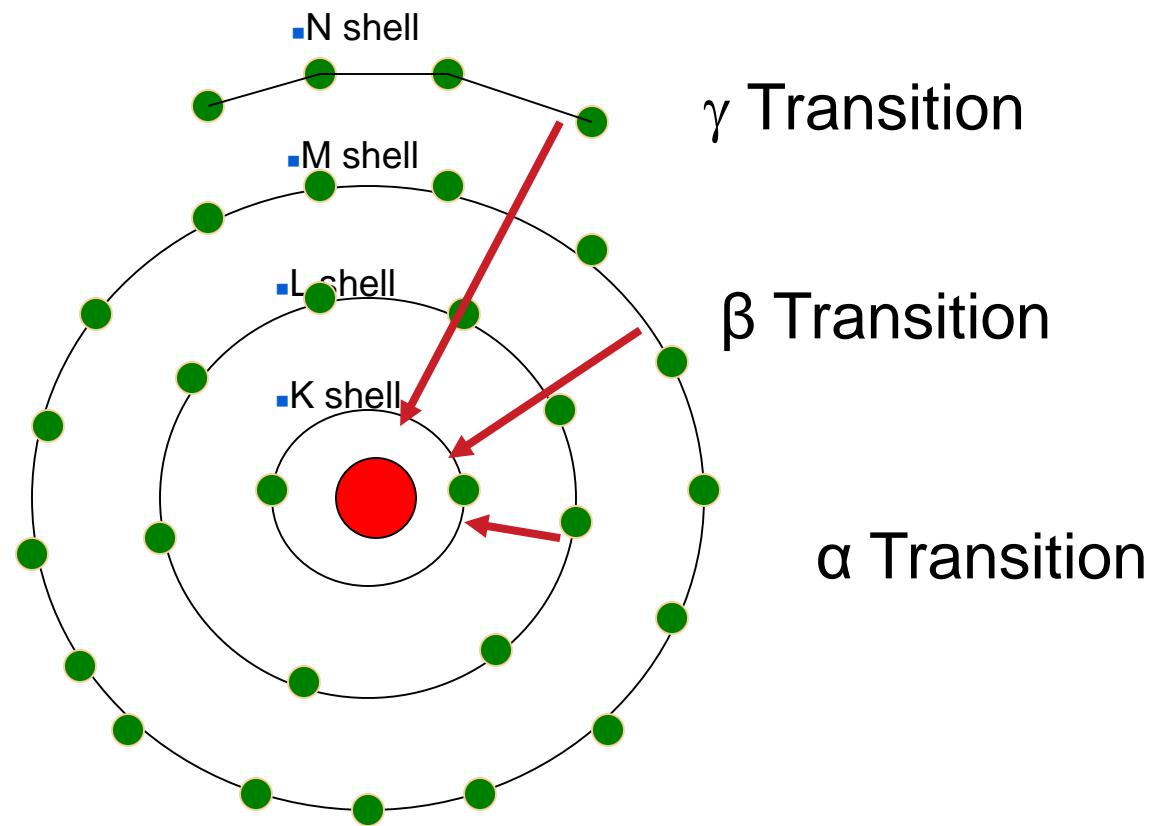
X-ray Generation



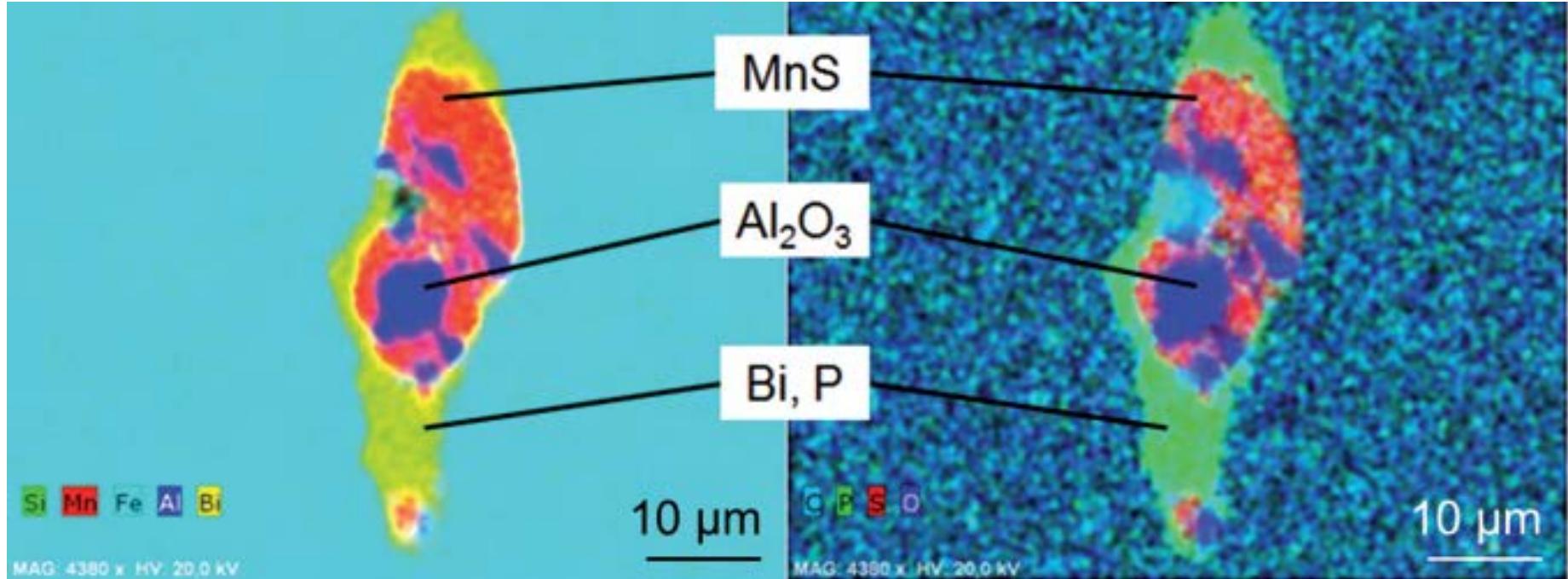
Niels Bohr
1885-1962
Danish
Nobel Prize 1922

Bohr, Niels (1913). "On the Constitution of Atoms and Molecules, Part III Systems containing several nuclei". *Philosophical Magazine*; **26** (155): 857–875

Energy-Dispersive X-Ray Spectroscopy

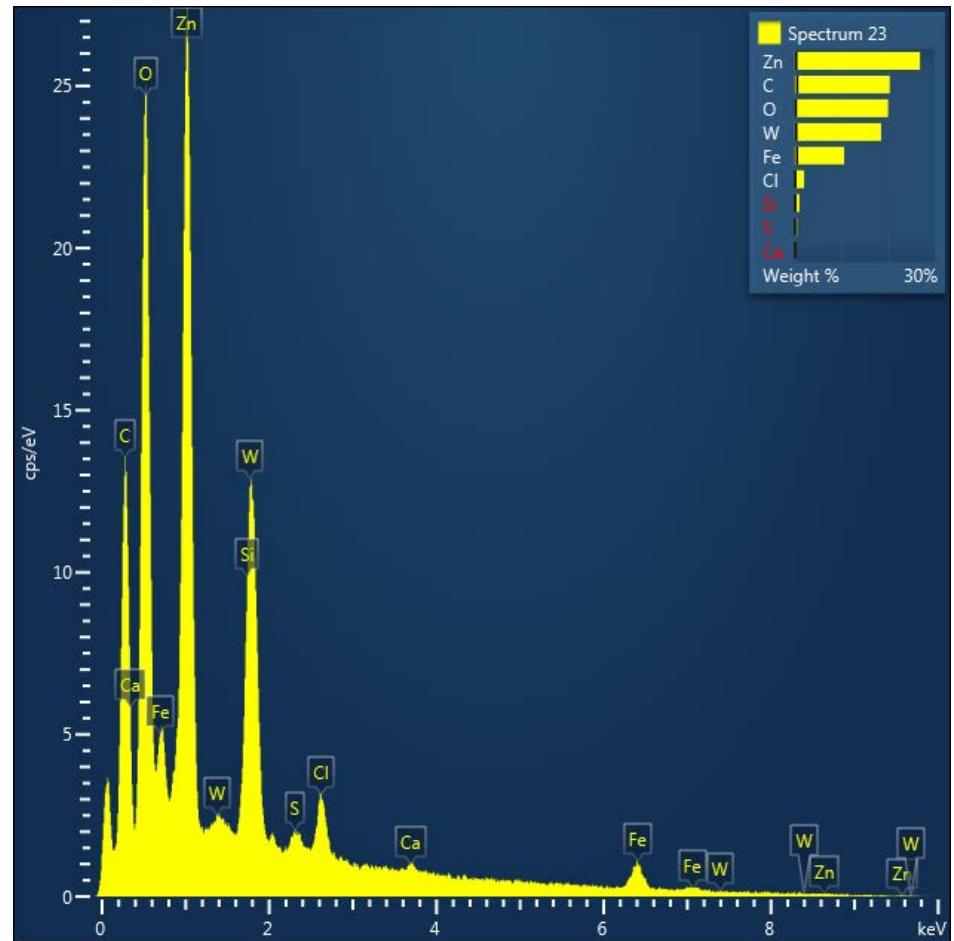
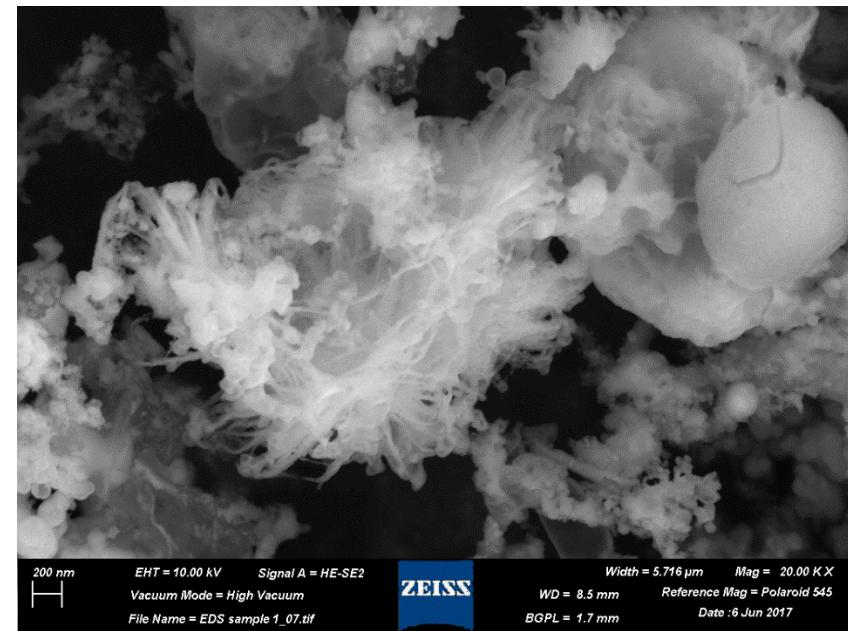


Characterization of Non-metallic Inclusions in Steel using EDS



EDS mapping of the conspicuous mixed inclusion in a mechanically polished steel sample (16MnCr5 grade). The core of the mixed inclusion consists of the "typical" inclusion types MnS (red) and Al₂O₃ (blue) whereas the surrounding bright phase contains the elements Bi (yellow) and P (green).

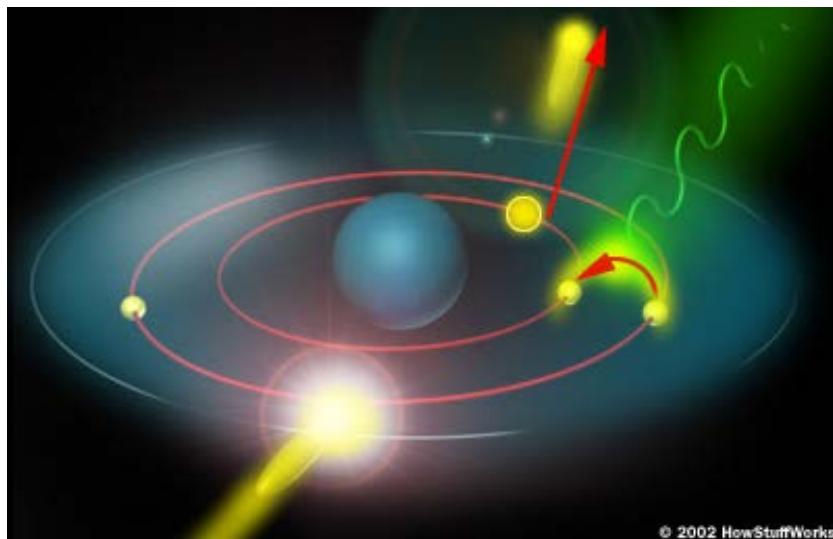
Energy-Dispersive X-Ray Spectroscopy



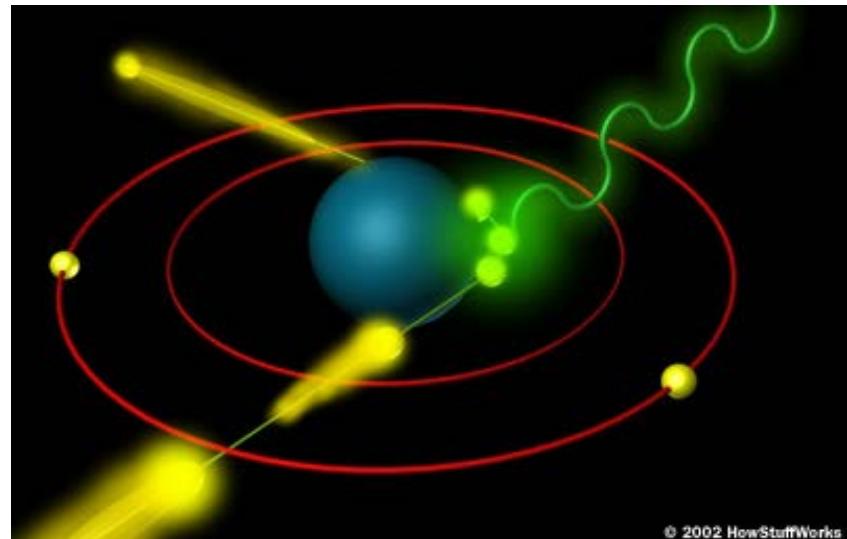
How X-rays (Photons) are Generated



Inelastic Scattering – Secondary Electron



Elastic Scattering – Backscattered Electron



The primary electron interacts with the atom, knocking an electron out of a lower orbital. A higher orbital electron fills the empty position, releasing a (characteristic) photon of a known and measureable energy and wavelength

The primary electron is attracted to the atom nucleus. The electron course is altered as the electron passes the nucleus resulting a release of an X-ray photon (bremsstrahlung).

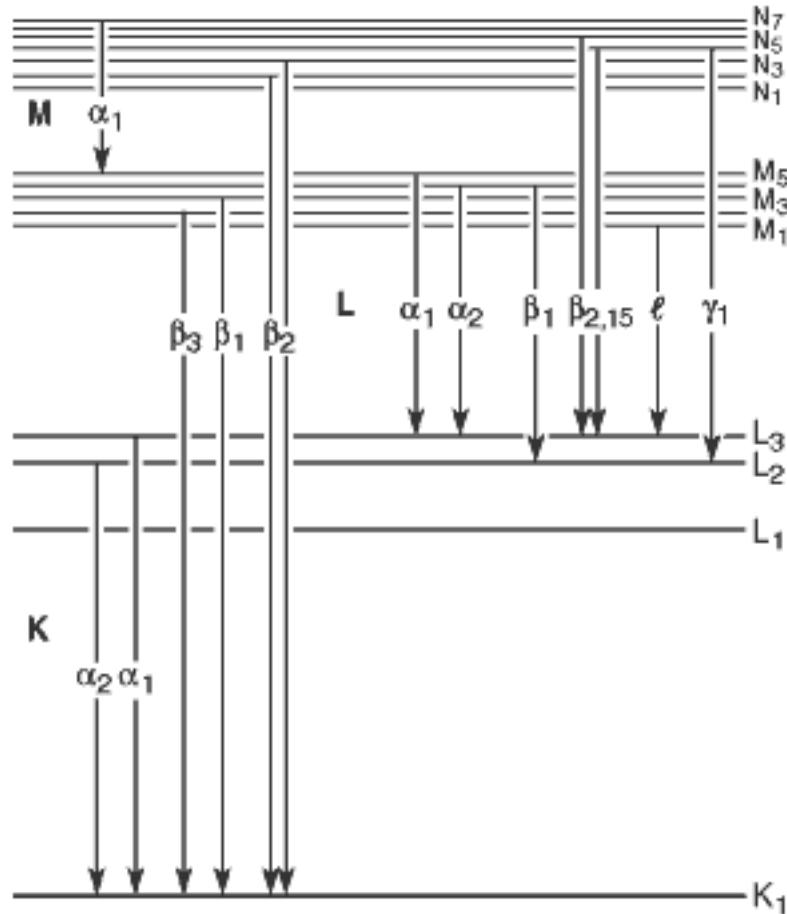
X-ray Line Nomenclature



Karl Manne Georg Siegbahn
1886 – 1978
Swedish
1924 Nobel Prize

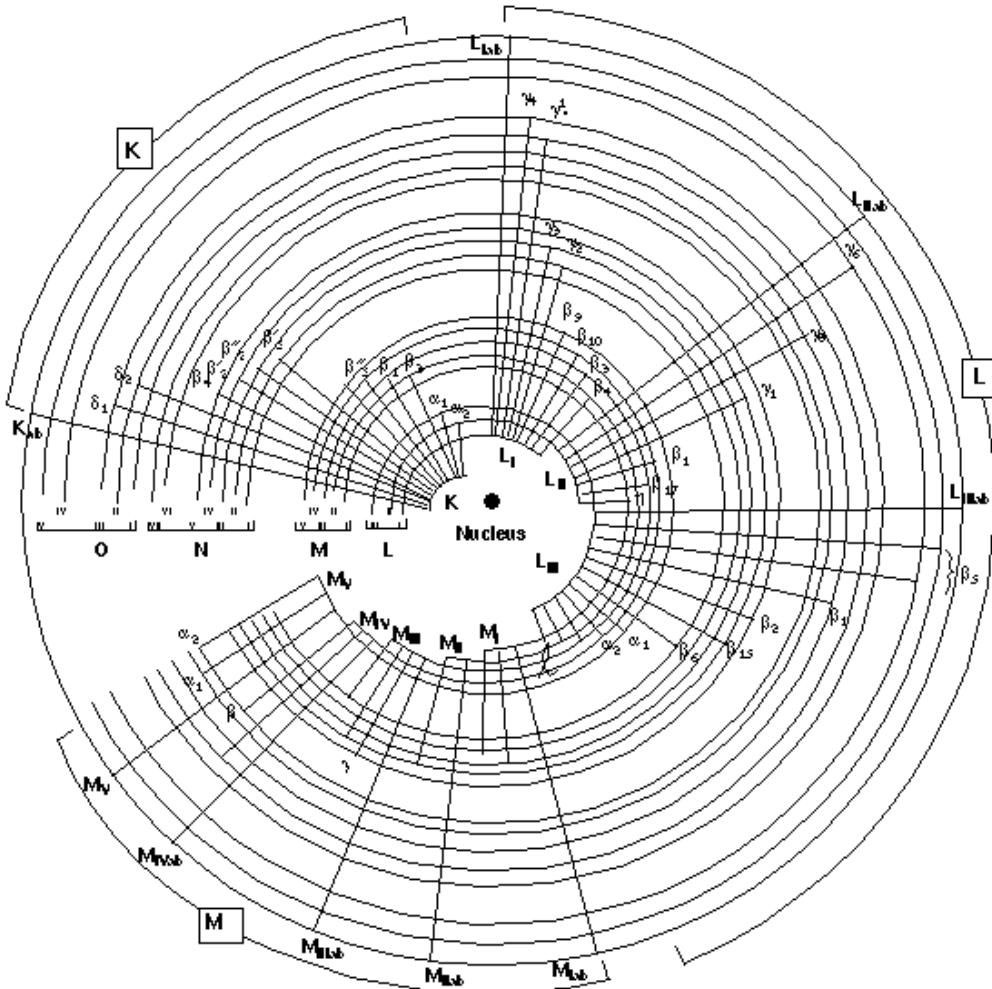
1. Atomic Symbol
2. Shell (KLMN)
3. Distance ($\alpha\beta\gamma\lambda$)

CaK α = Calcium, Kshell, L to K transition



Siegbahn Notation ARL

Energy Level Diagram of Electron Transitions



4. CORRESPONDENCE BETWEEN THE SIEGBAHN AND IUPAC NOTATIONS

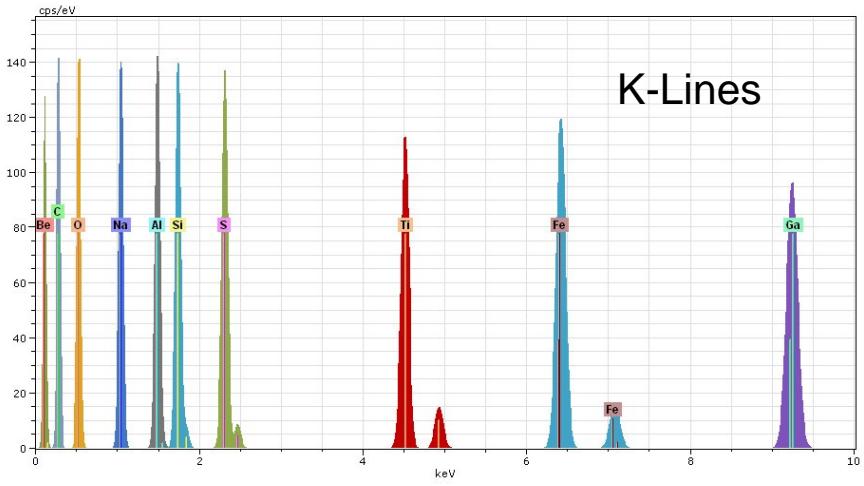
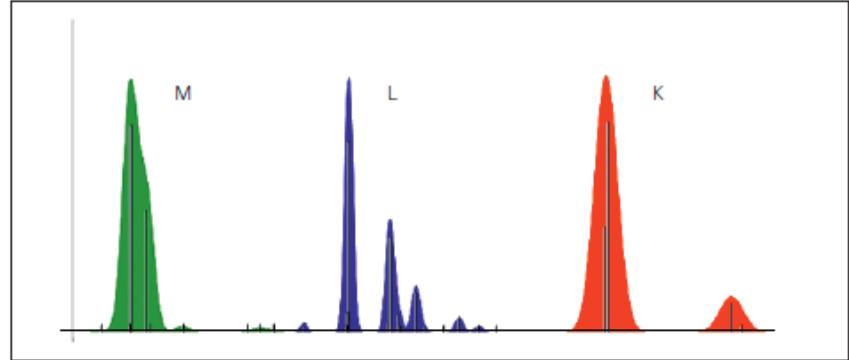
The IUPAC Notation is compared with the Siegbahn notation in the following table.

Table VIII.2. Correspondence between Siegbahn and IUPAC notation diagram lines

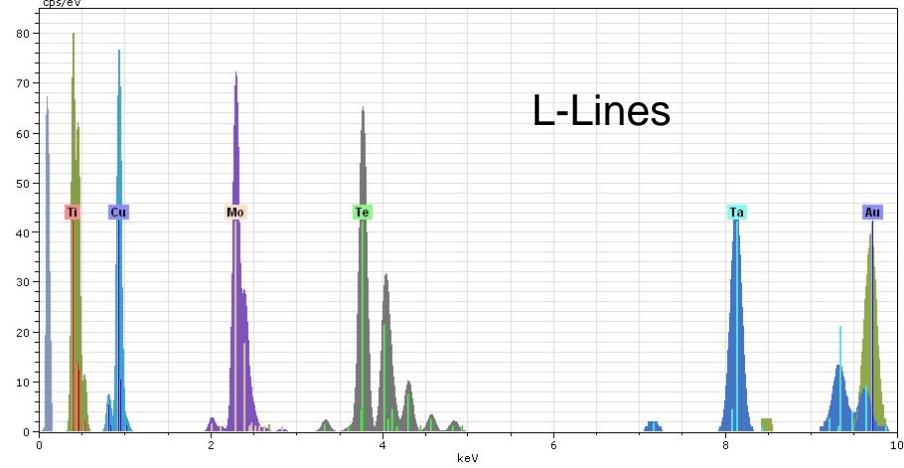
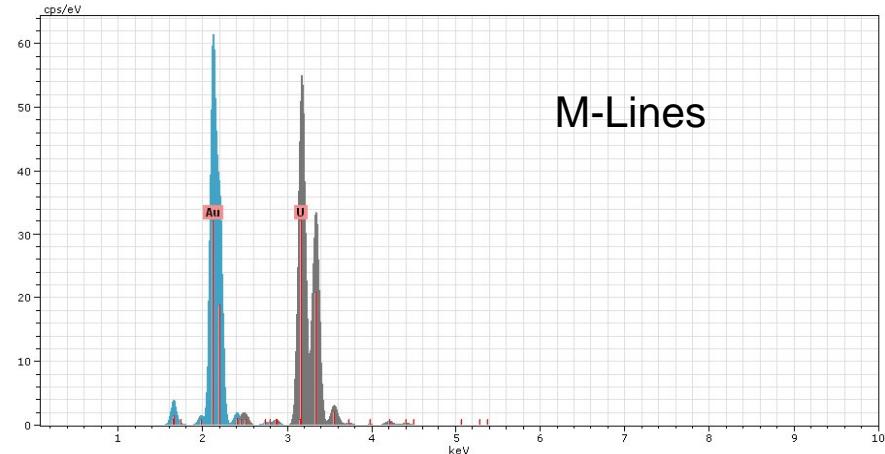
Siegbahnen	IUPAC	Siegbahnen	IUPAC	Siegbahnen	IUPAC	Siegbahnen	IUPAC
$K\alpha_1$	K-L ₃	$L\alpha_1$	L ₃ -M ₅	$L\gamma_1$	L ₂ -N ₄	$M\alpha_1$	M ₅ -N ₇
$K\alpha_2$	K-L ₂	$L\alpha_2$	L ₃ -M ₄	$L\gamma_2$	L ₁ -N ₂	$M\alpha_2$	M ₅ -N ₆
$K\beta_1$	K-M ₃	$L\beta_1$	L ₂ -M ₄	$L\gamma_3$	L ₁ -N ₃	$M\beta$	M ₄ -N ₆
$K^I\beta_2$	K-N ₃	$L\beta_2$	L ₃ -N ₅	$L\gamma_4$	L ₁ -O ₃	$M\gamma$	M ₃ -N ₅
$K^{II}\beta_2$	K-N ₂	$L\beta_3$	L ₁ -M ₃	$L\gamma_4'$	L ₁ -O ₂	$M\zeta$	M _{4,5} -N _{2,3}
$K\beta_3$	K-M ₂	$L\beta_4$	L ₁ -M ₂	$L\gamma_5$	L ₂ -N ₁		
$K^I\beta_4$	K-N ₅	$L\beta_5$	L ₃ -O _{4,5}	$L\gamma_6$	L ₂ -O ₄		
$K^{II}\beta_4$	K-N ₄	$L\beta_6$	L ₃ -N ₁	$L\gamma_8$	L ₂ -O ₁		
$K\beta_{4x}$	K-N ₄	$L\beta_7$	L ₃ -O ₁	$L\gamma_8'$	L ₂ -N ₀₍₇₎		
$K^I\beta_5$	K-M ₅	$L\beta_7'$	L ₃ -N _{0,7}	$L\gamma_9$	L ₂ -M ₁		
$K^{II}\beta_5$	K-M ₄	$L\beta_9$	L ₁ -M ₅	$L\gamma$	L ₃ -M ₁		
		$L\beta_{10}$	L ₁ -M ₄	$L\gamma$	L ₃ -M ₃		
		$L\beta_{15}$	L ₃ -N ₄	$L\gamma$	L ₃ -M ₂		
		$L\beta_{17}$	L ₂ -M ₃	$L\gamma$	L ₃ -N _{0,7}		
				$L\gamma$	L ₂ -N ₀₍₇₎		

In the case of unresolved lines, such as K-L₂ and K-L₃, the recommended IUPAC notation is K-L_{2,3}.

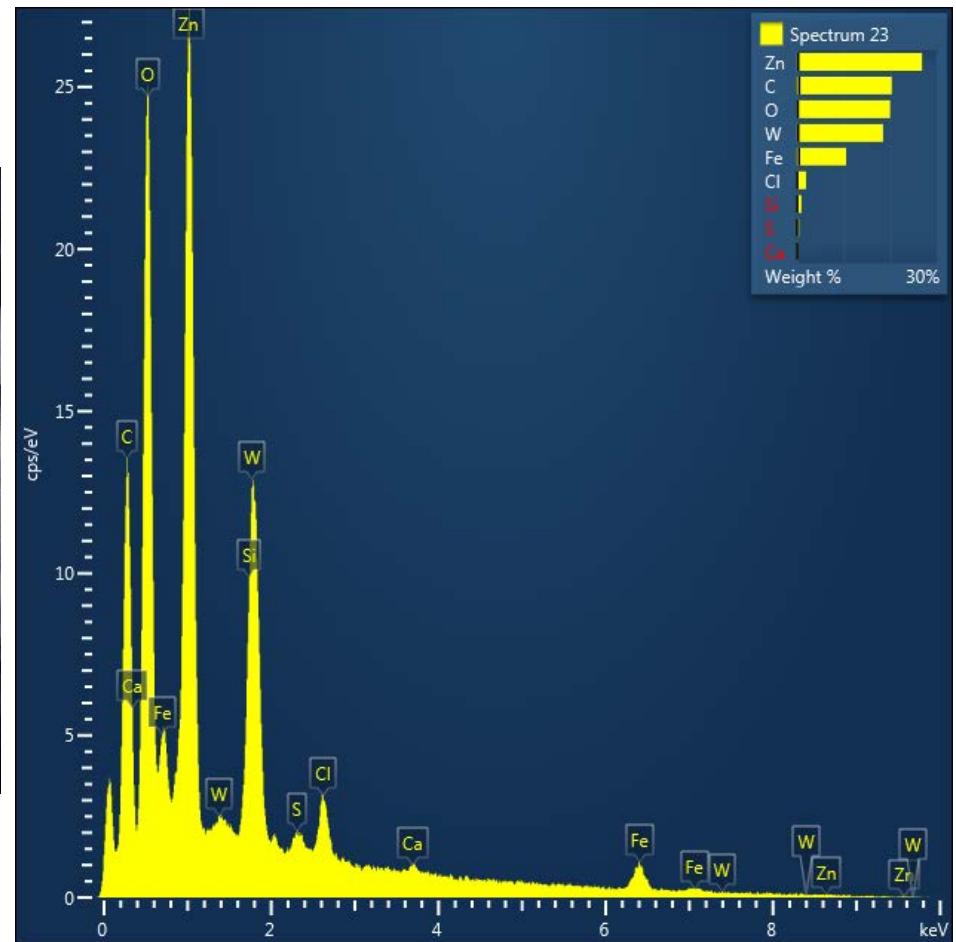
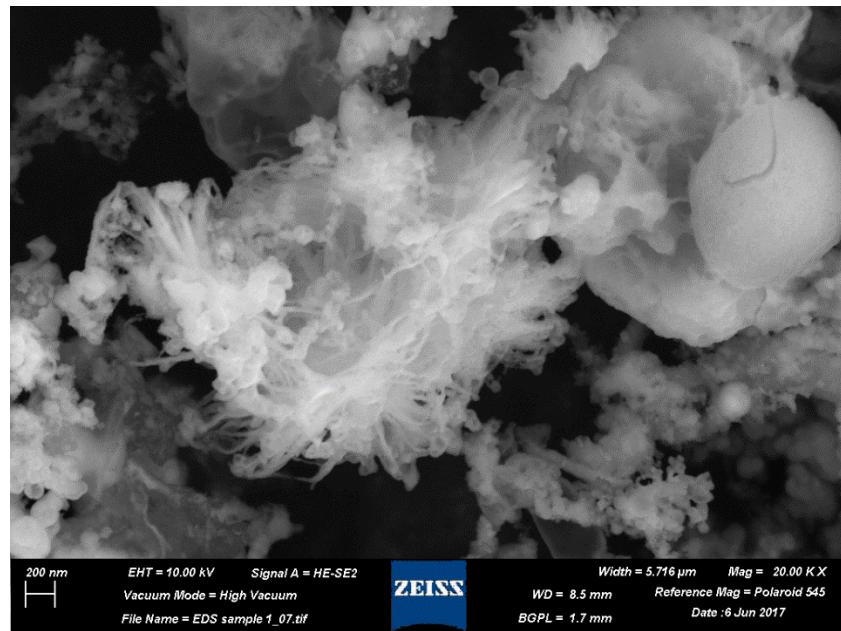
Typical X-ray Peak Shapes



At 15kV accelerating voltage we can see the entire Periodic Table using K, L and M lines.



Energy-Dispersive X-Ray Spectroscopy

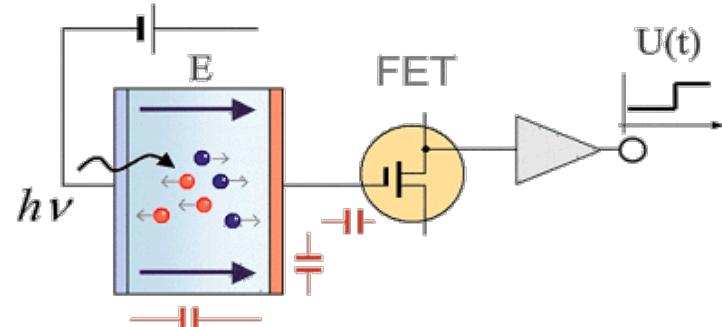


How Solid State Detectors Work

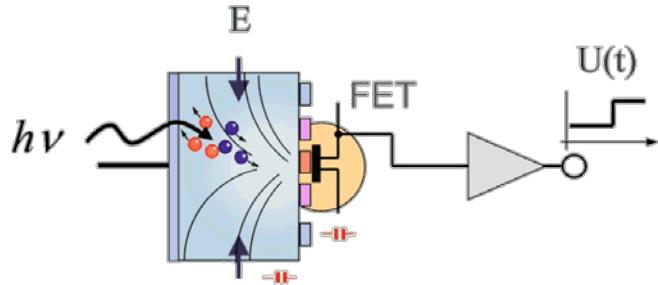


Si(Li)
or
HpGe

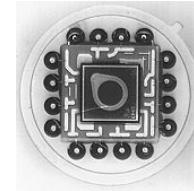
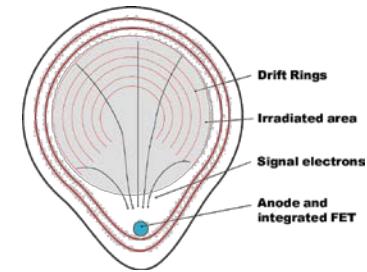
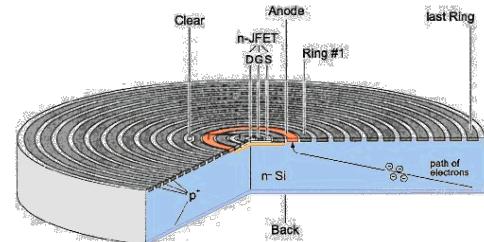
SDD



$$n_e = h \frac{\nu}{\epsilon}$$



$$n_e = h \frac{\nu}{\epsilon}$$



Summary

The scanning electron microscope (SEM) is an exceptionally versatile analytical tool, with resolution better than 1 nanometer.

The SEM produces images by scanning the surface of a sample with a focused beam of electrons.

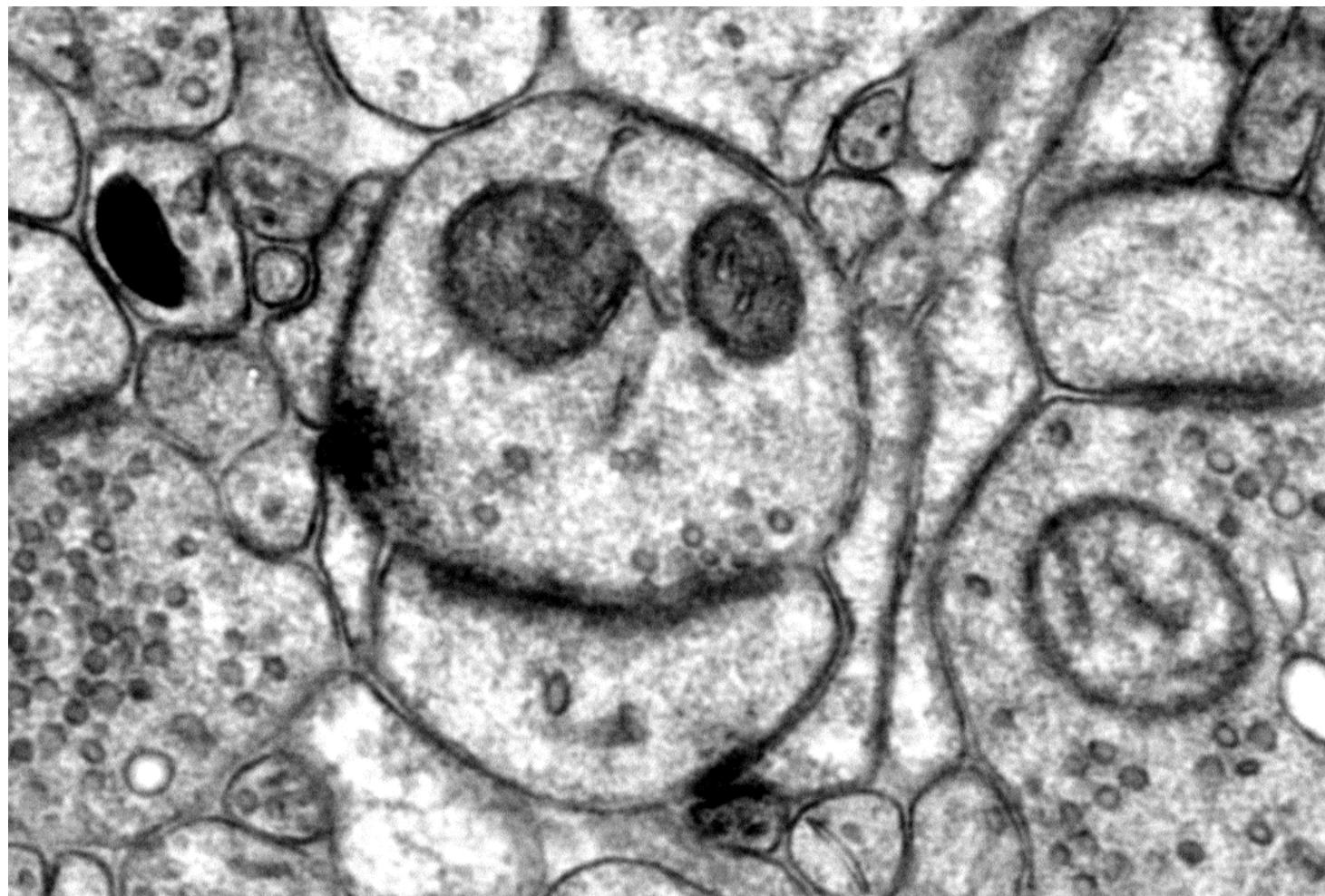
These electrons interact with atoms in the sample, producing various signals that contain information about the sample's surface topography and composition.

Characteristic X-rays that are produced by the interaction of electrons with the sample may also be detected in an SEM equipped for energy-dispersive X-ray spectroscopy, EDS

Analysis of the x-ray signals can be used to map the distribution and estimate the abundance of elements in the sample.

SEM/EDS systems are some of the most powerful and versatile analytical tools available.

SEM produces Happy, Stimulated Synapses



100 nm

EHT = 8.00 kV Signal A = BSD4 A
Vacuum Mode = High Vacuum
WD = 8.4 mm
File Name = Brain section_30.tif



GEMINI SEM 300

Date :17 Aug 2017

Mag = 60.64 KX
Width = 1.885 µm
Reference Mag = Polaroid 545

